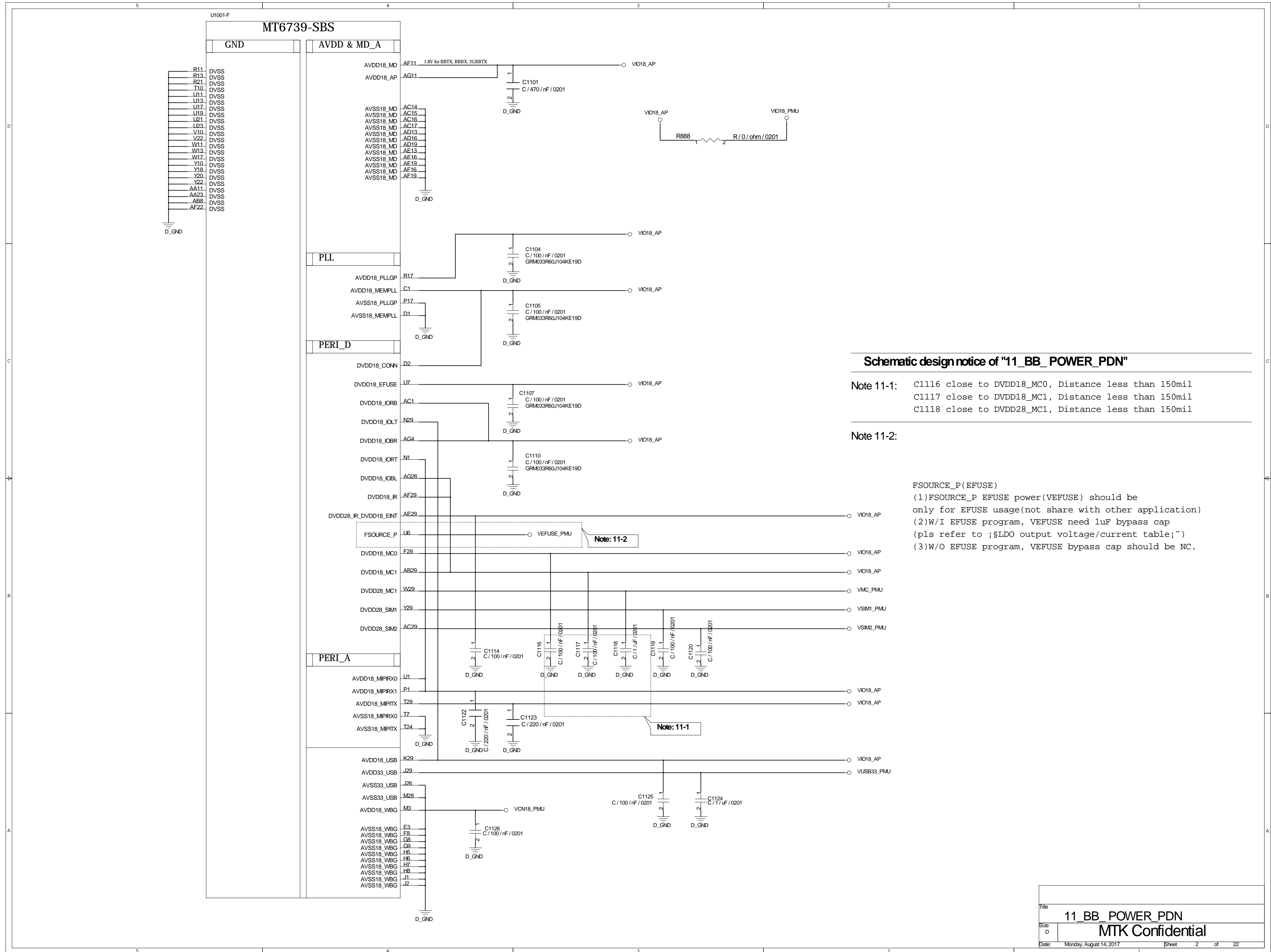


Schematic design notice of "10\_BB\_POWER\_PDN" page.

**Note 10-1:** Differential pair of DVDD\_DVFS remote sense must be close to BB's ball. Remote sense trace with GND shielding to PMIC (Differential)

**Note 10-2:** Differential pair of DVDD\_TOP remote sense must be close to BB's ball. Remote sense trace with GND shielding to PMIC (Differential)

**Note 10-3:** Differential pair of DVDD\_MODEM1\_BUCK remote sense must be close to BB's ball. Remote sense trace with GND shielding to PMIC (Differential)

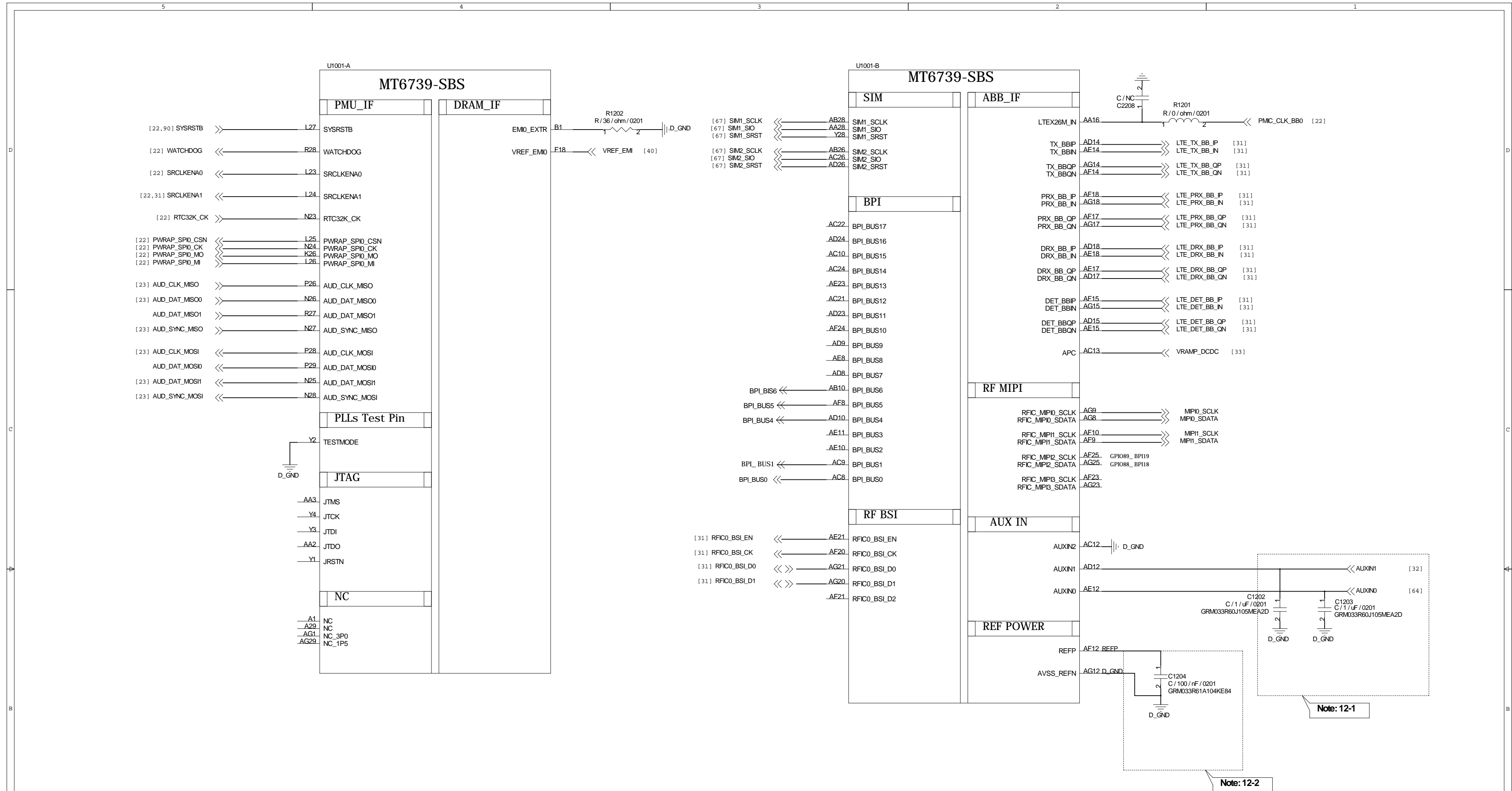


**Schematic design notice of "11\_BB\_POWER\_PDN"**

**Note 11-1:** C1116 close to DVDD18\_MC0, Distance less than 150mil  
 C1117 close to DVDD18\_MC1, Distance less than 150mil  
 C1118 close to DVDD28\_MC1, Distance less than 150mil

**Note 11-2:**

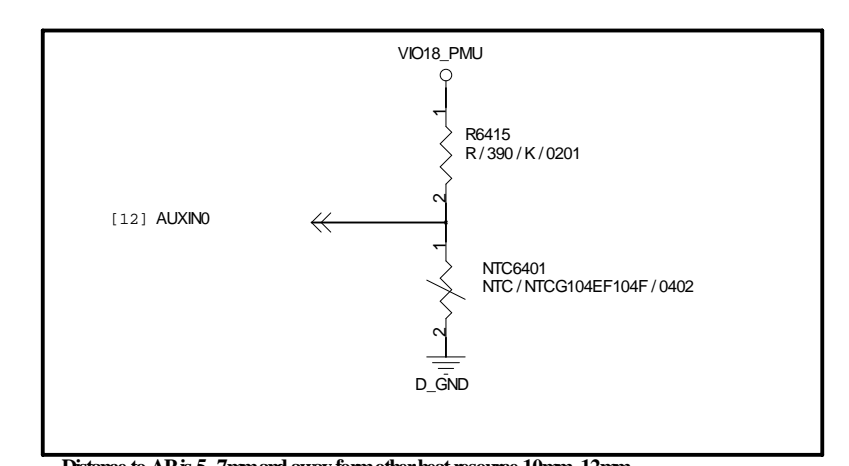
FSOURCE\_P(EFUSE)  
 (1)FSOURCE\_P EFUSE power(VEFUSE) should be only for EFUSE usage(not share with other application)  
 (2)W/I EFUSE program, VEFUSE need 1uF bypass cap (pls refer to ;SLDO output voltage/current table;")  
 (3)W/O EFUSE program, VEFUSE bypass cap should be NC.



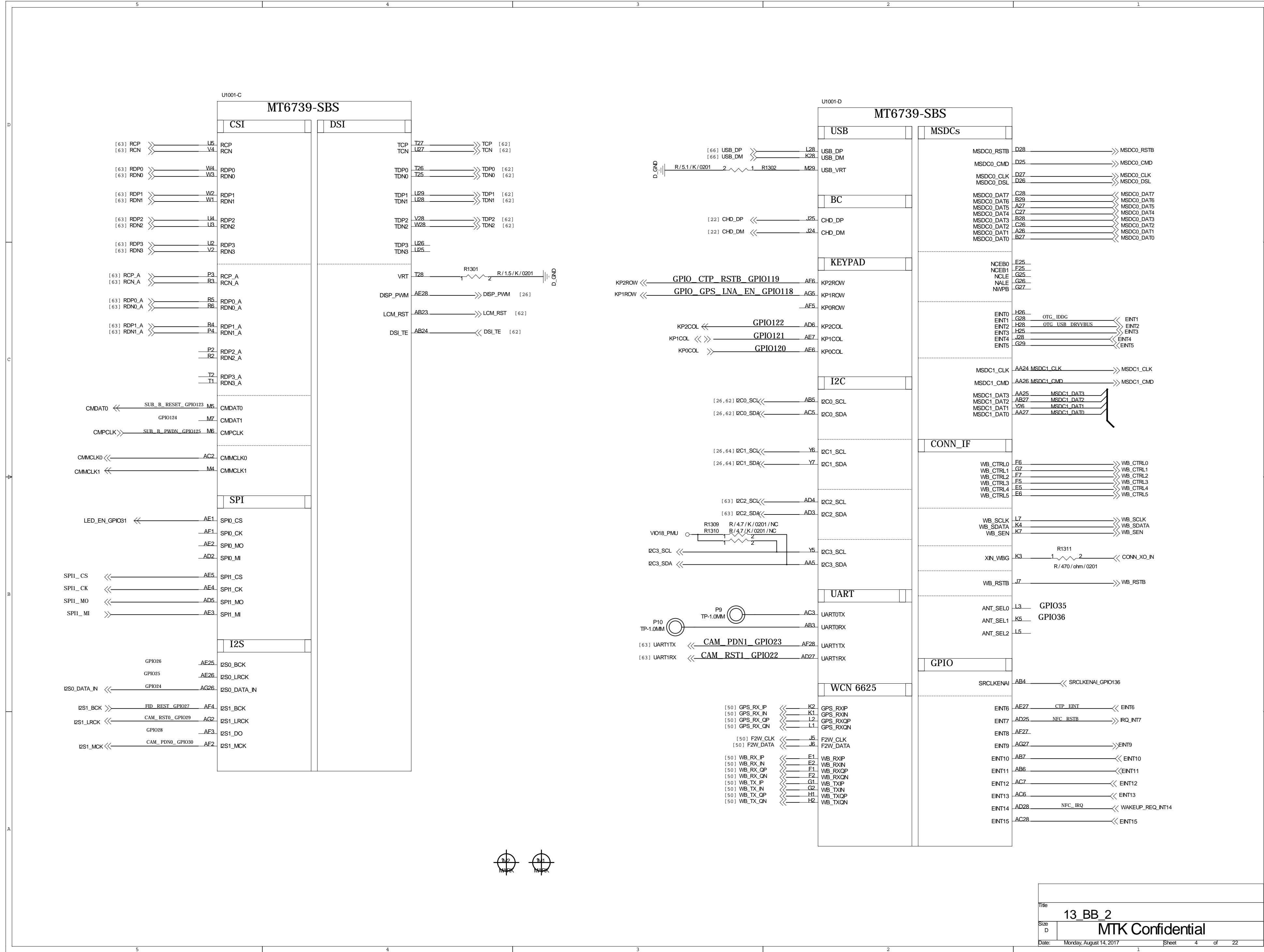
**Schematic design notice of "12\_BB\_1" page.**

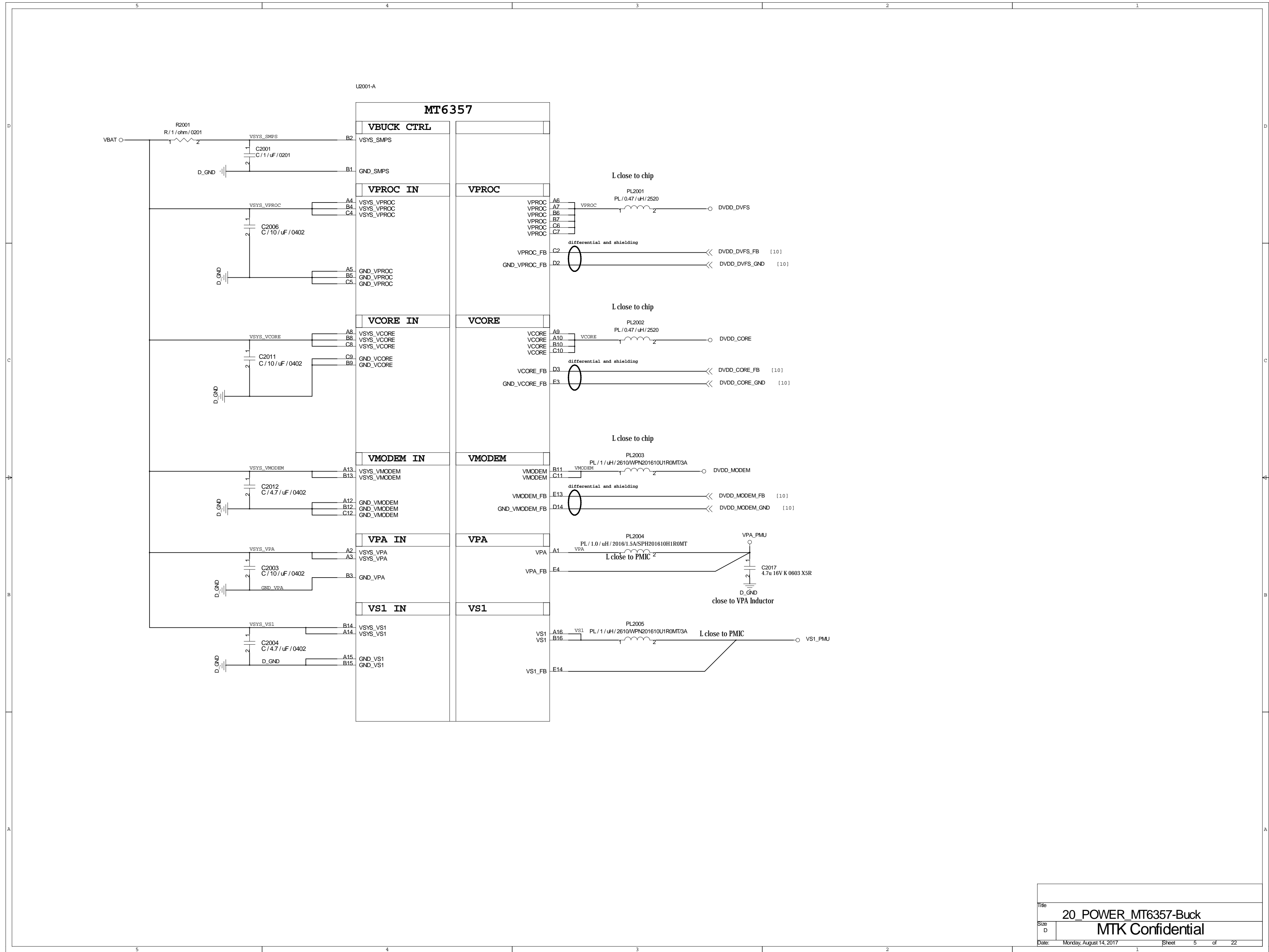
- Note 12-1: To shunt a 1uF capacitor in the AUXIN ADC input to prevent noise coupling. It should be placed as close to BB as possible. Connect the unused AUX ADC input to GND.
- Note 12-2: The de-coupling cap. for REFP (AF12 ball) have to be placed as close to BB as possible.

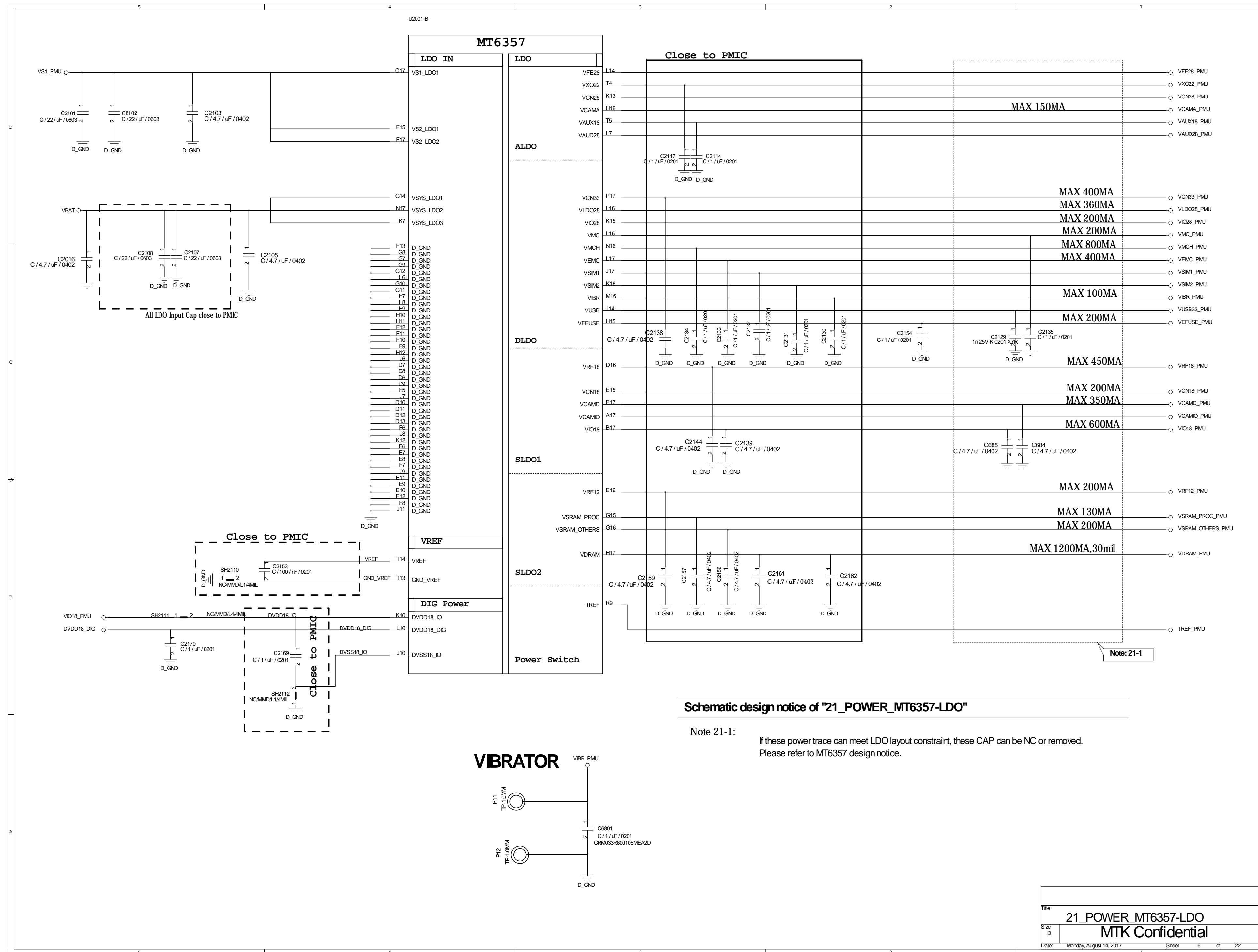
**Thermistor / To sense board level temperature**



Distance to AP is 5-7mm and away from other heat resource 10mm-12mm

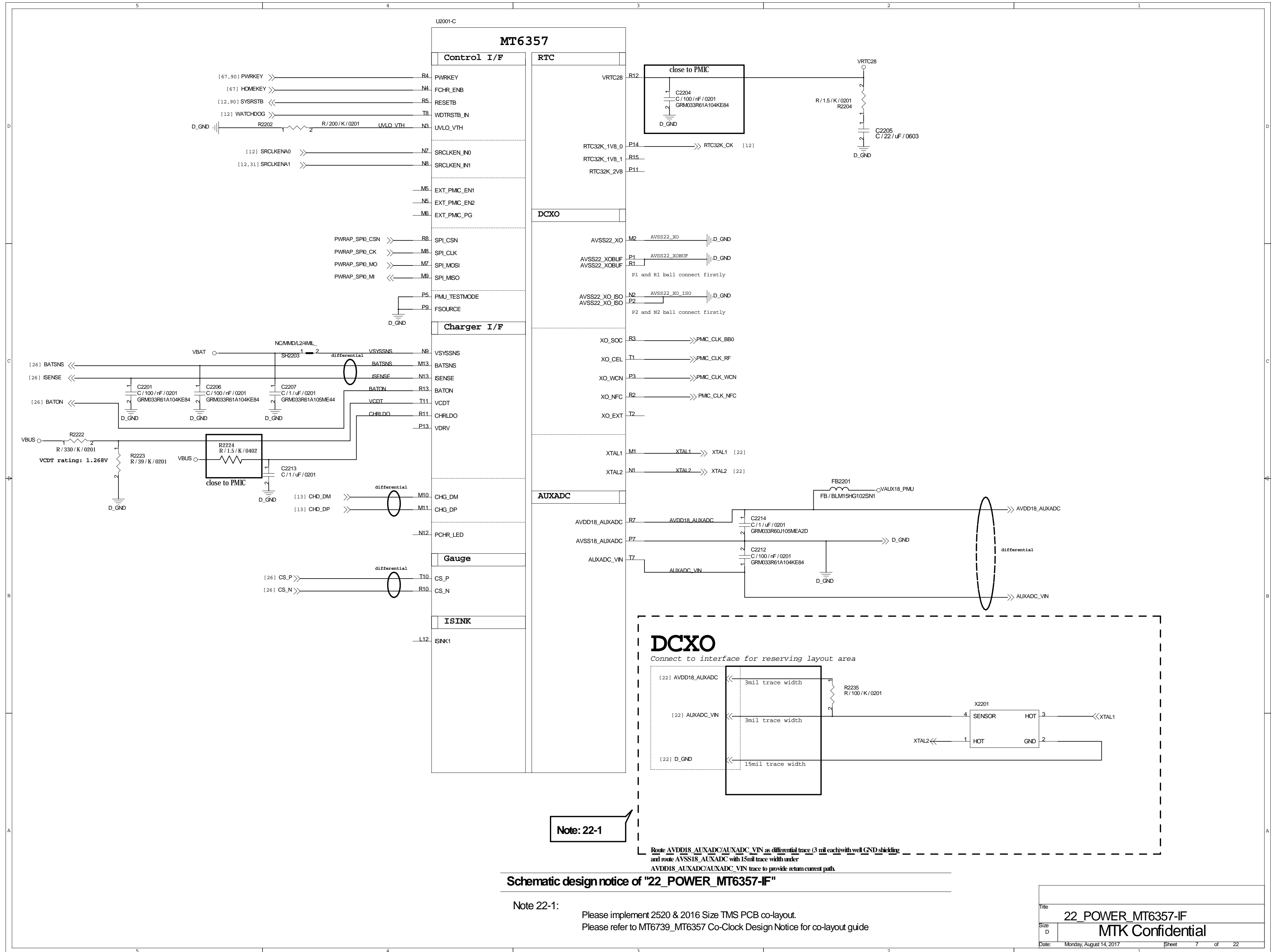






**Schematic design notice of "21\_POWER\_MT6357-LDO"**

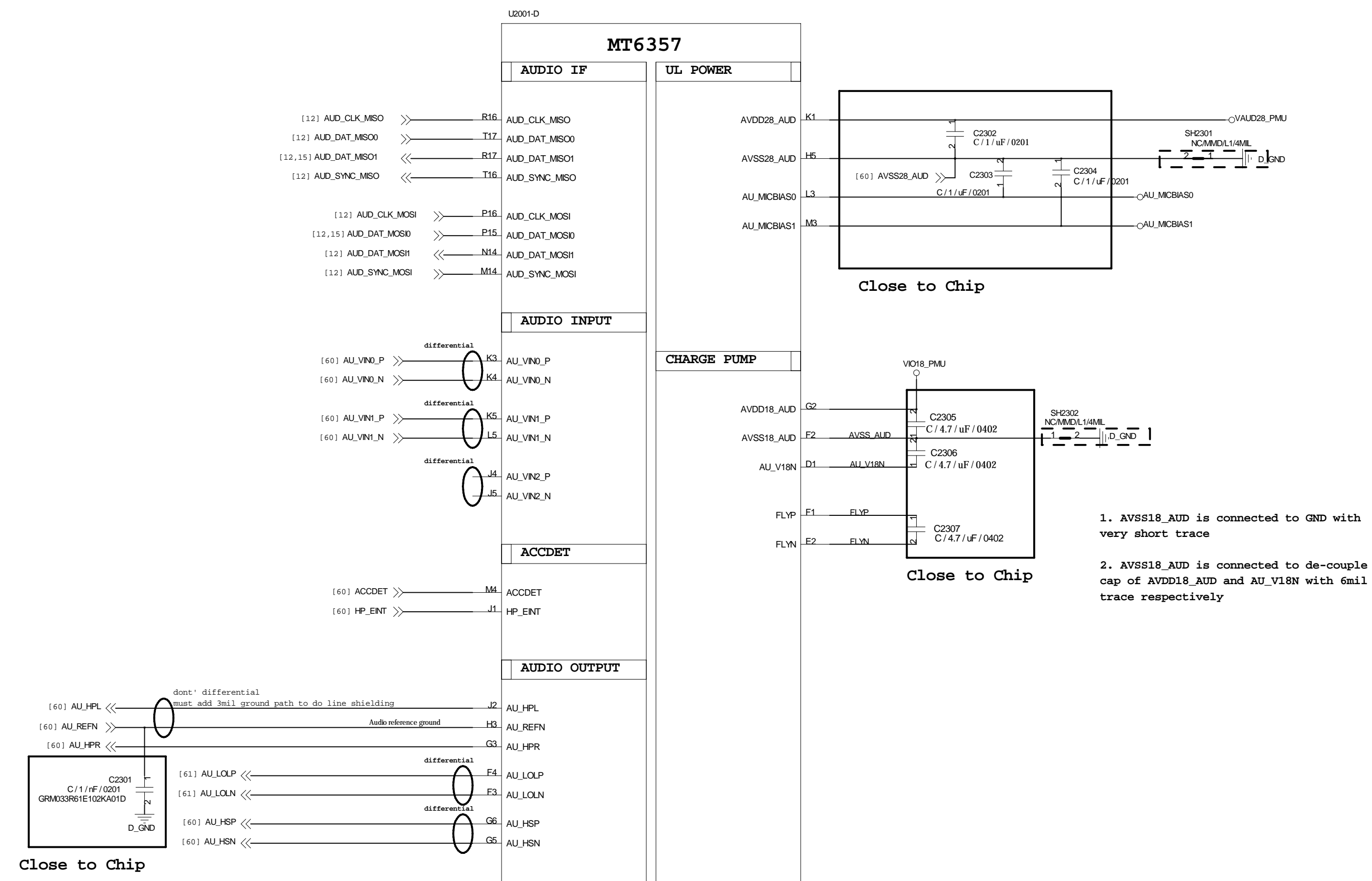
Note 21-1: If these power trace can meet LDO layout constraint, these CAP can be NC or removed. Please refer to MT6357 design notice.



**Schematic design notice of "22\_POWER\_MT6357-IF"**

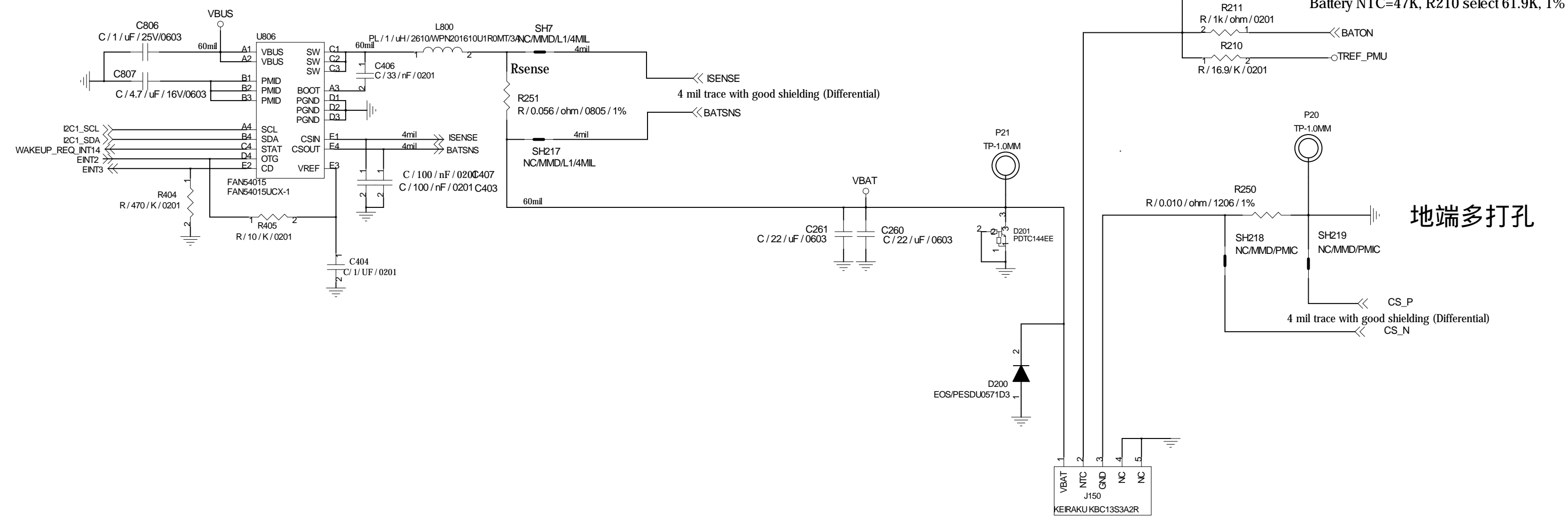
Note 22-1: Please implement 2520 & 2016 Size TMS PCB co-layout. Please refer to MT6739\_MT6357 Co-Clock Design Notice for co-layout guide

File	22_POWER_MT6357-IF
Size	MTK Confidential
Date	Monday, August 14, 2017
Sheet	7 of 22

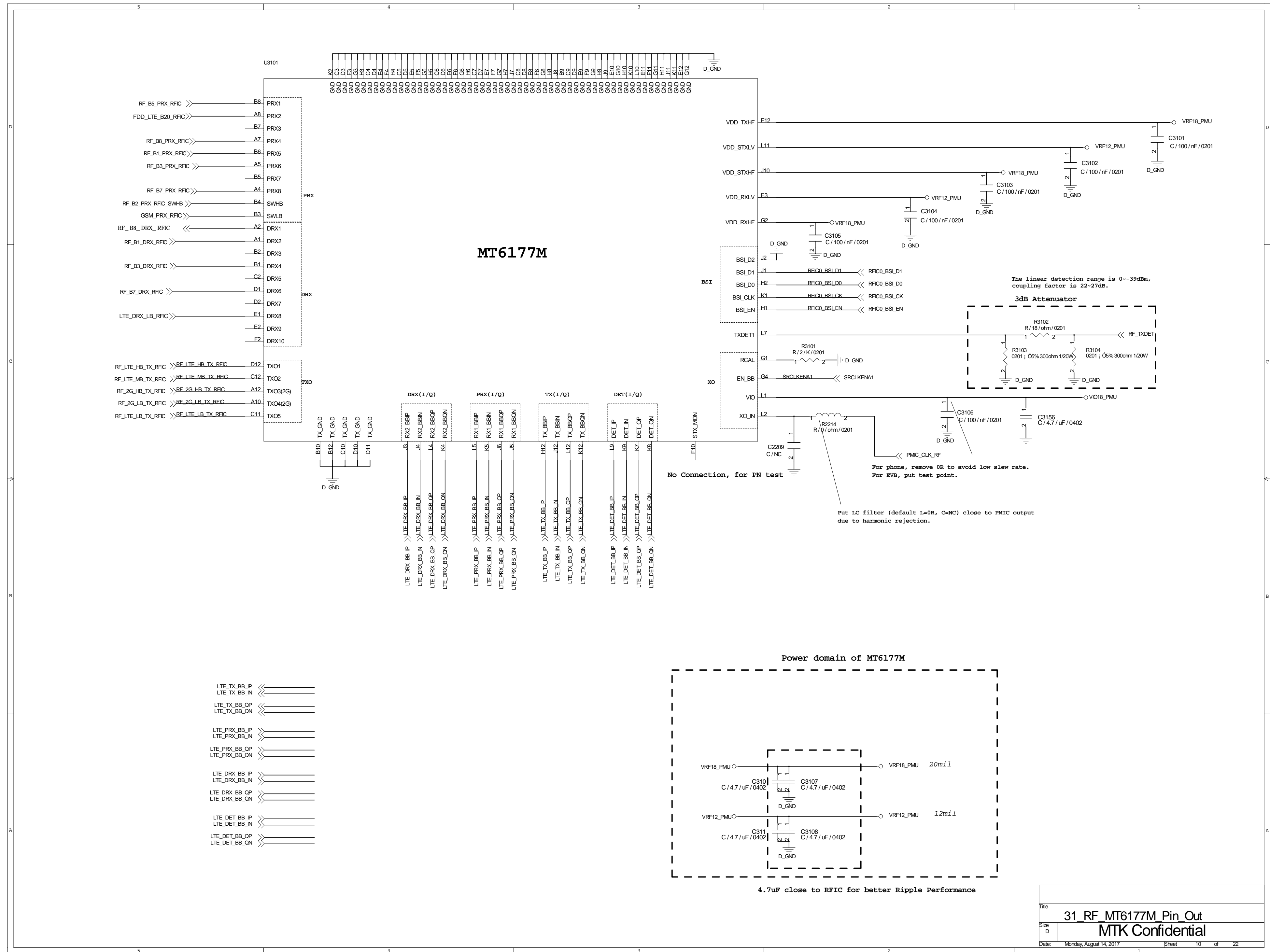


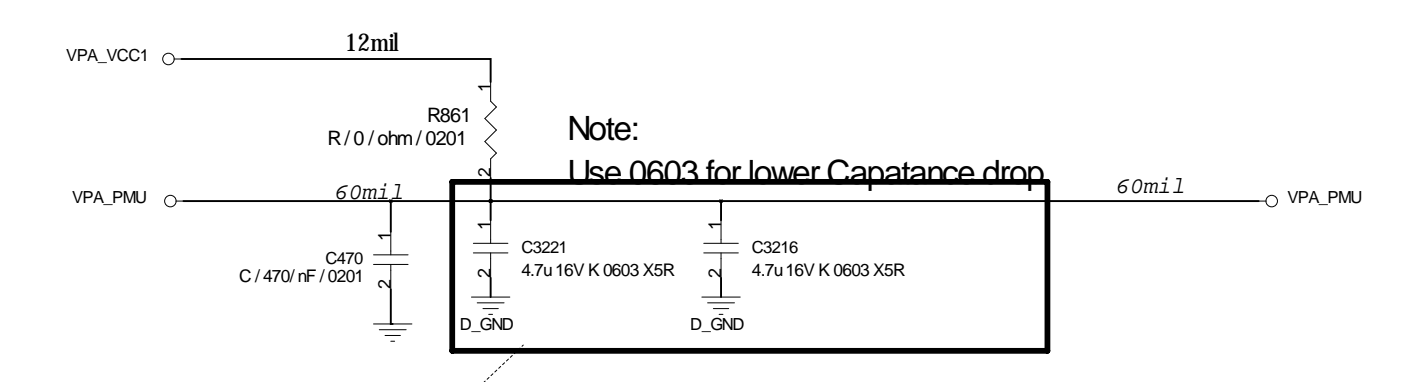
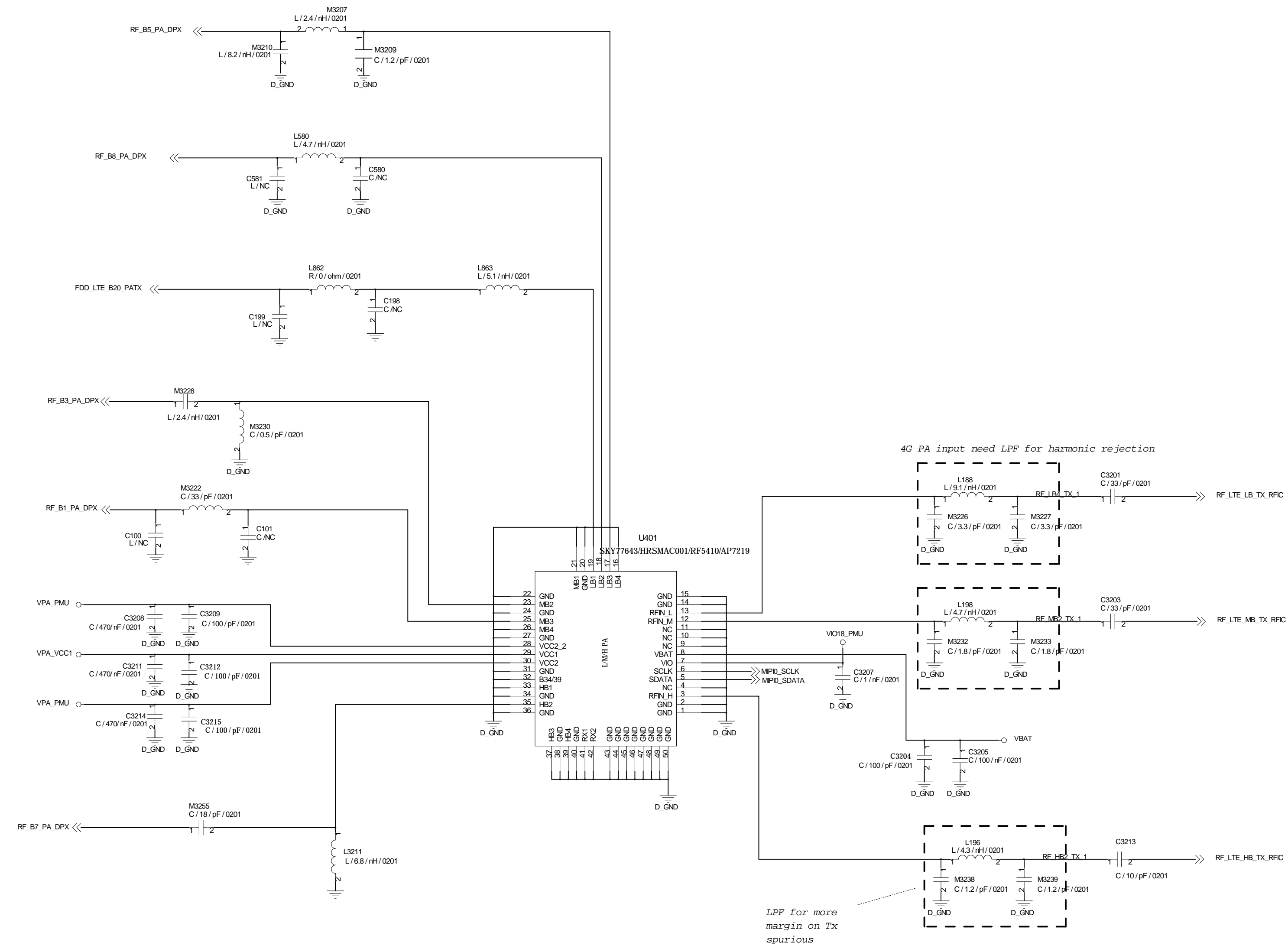


# switching Li-Ion battery charger

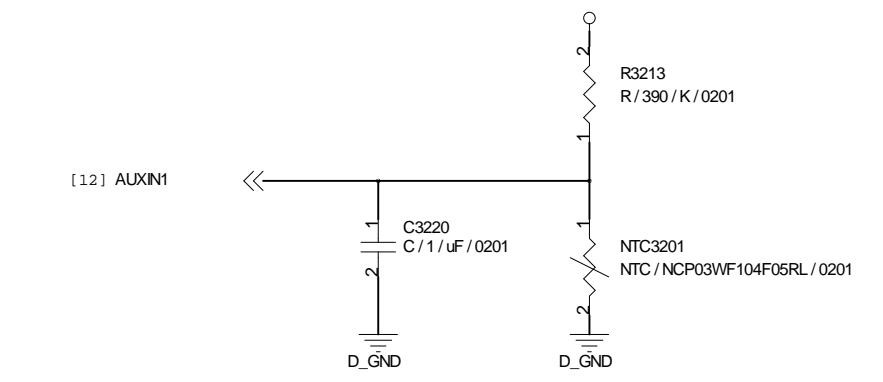


## BATTERY CONNECTOR

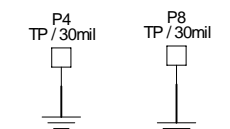
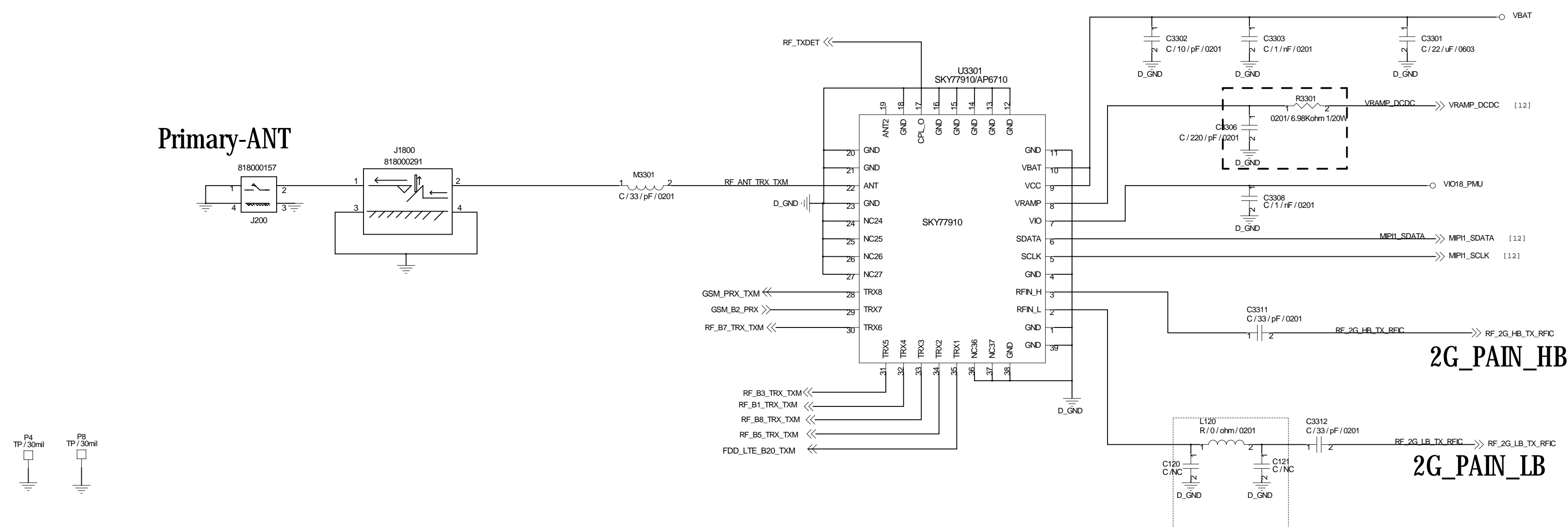




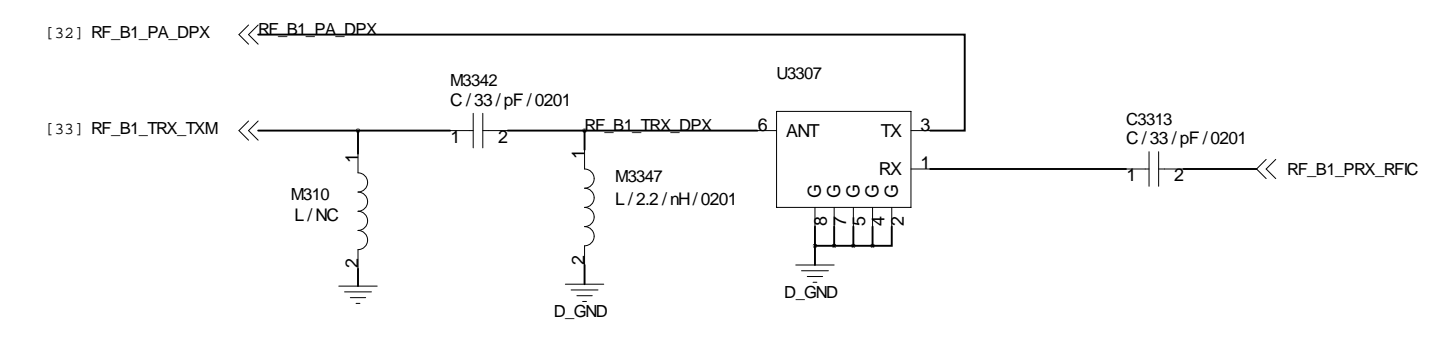
Note:  
Reserve one tuning cap. For PMIC VPA total cap requirement, the total cap at RF side should be in 6.2uF +/-10%.



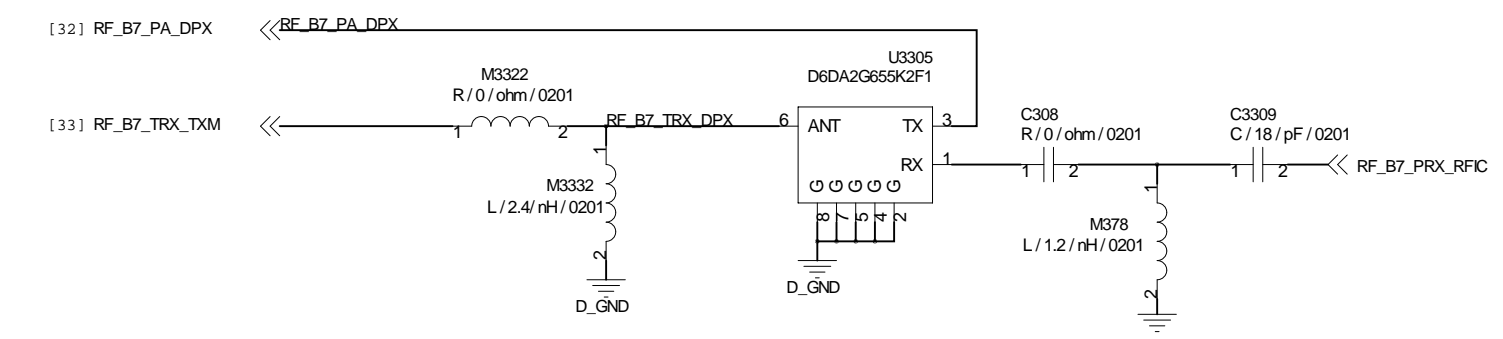
### Primary-ANT



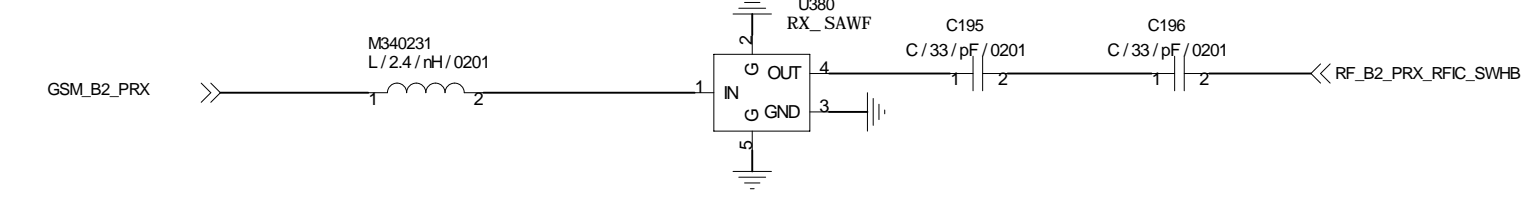
### WCDMA\_LTE\_B1 TRX



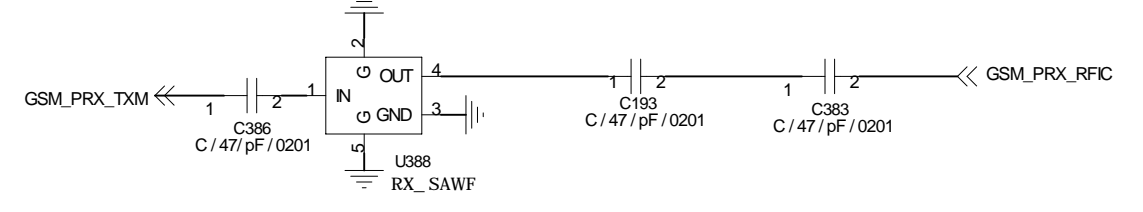
### LTE\_B7 TRX



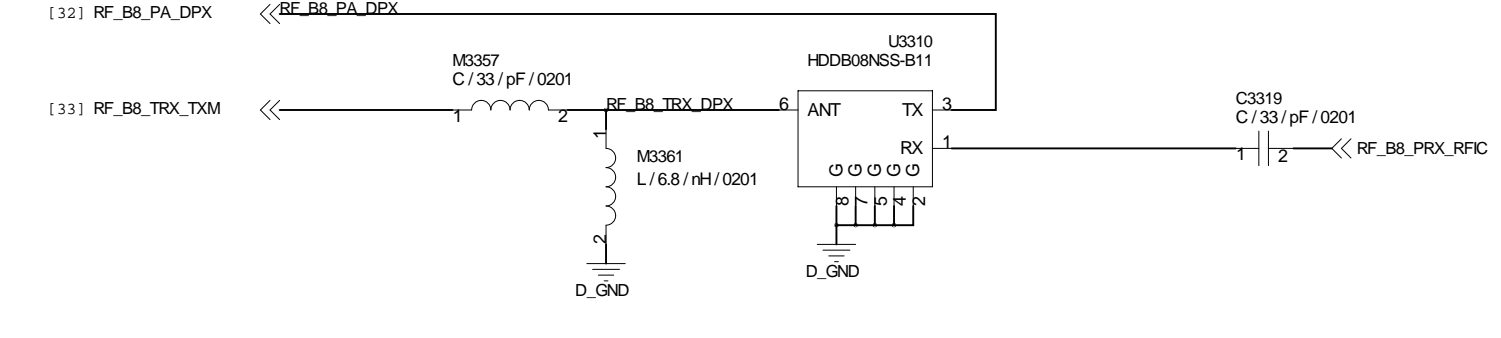
### GSM\_B2\_PRX



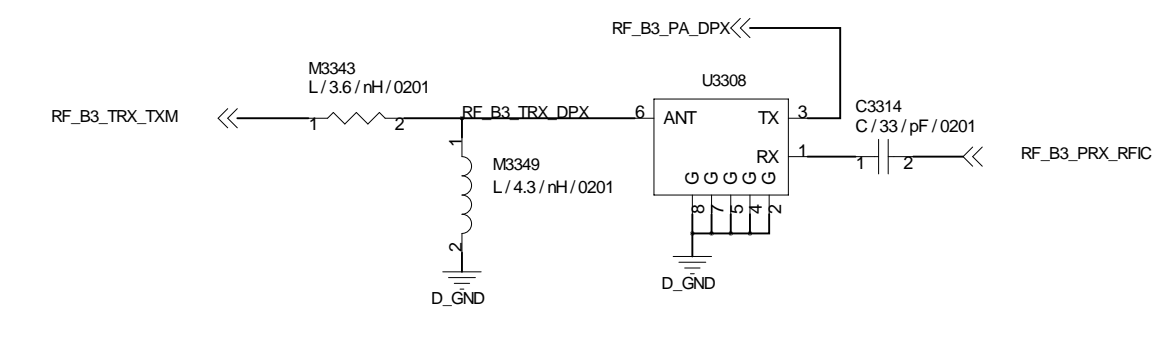
### GSM\_B5



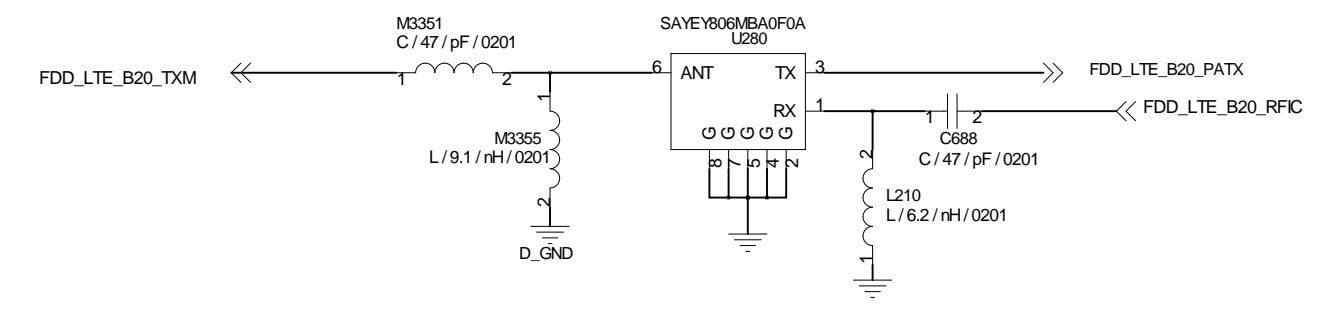
### GSM\_WCDMA\_B8 TRX



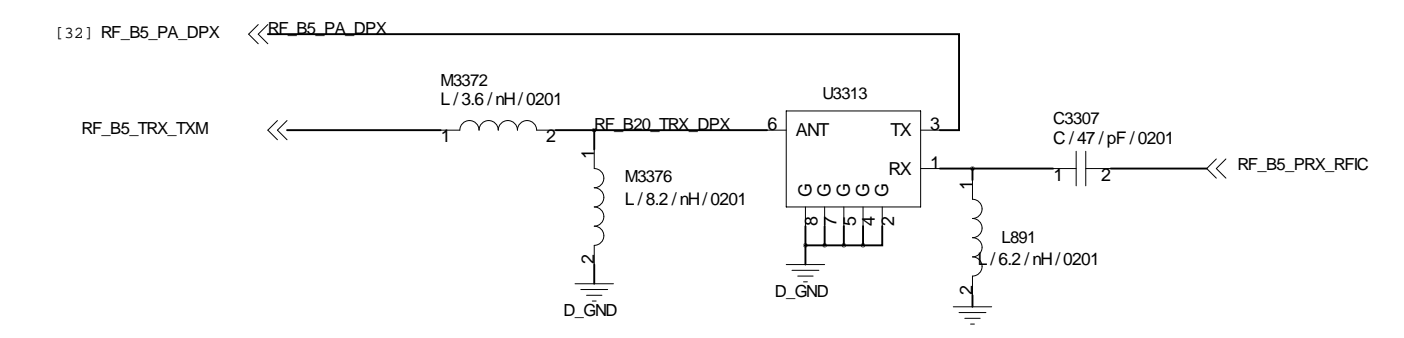
### GSM\_LTE\_B3 TRX



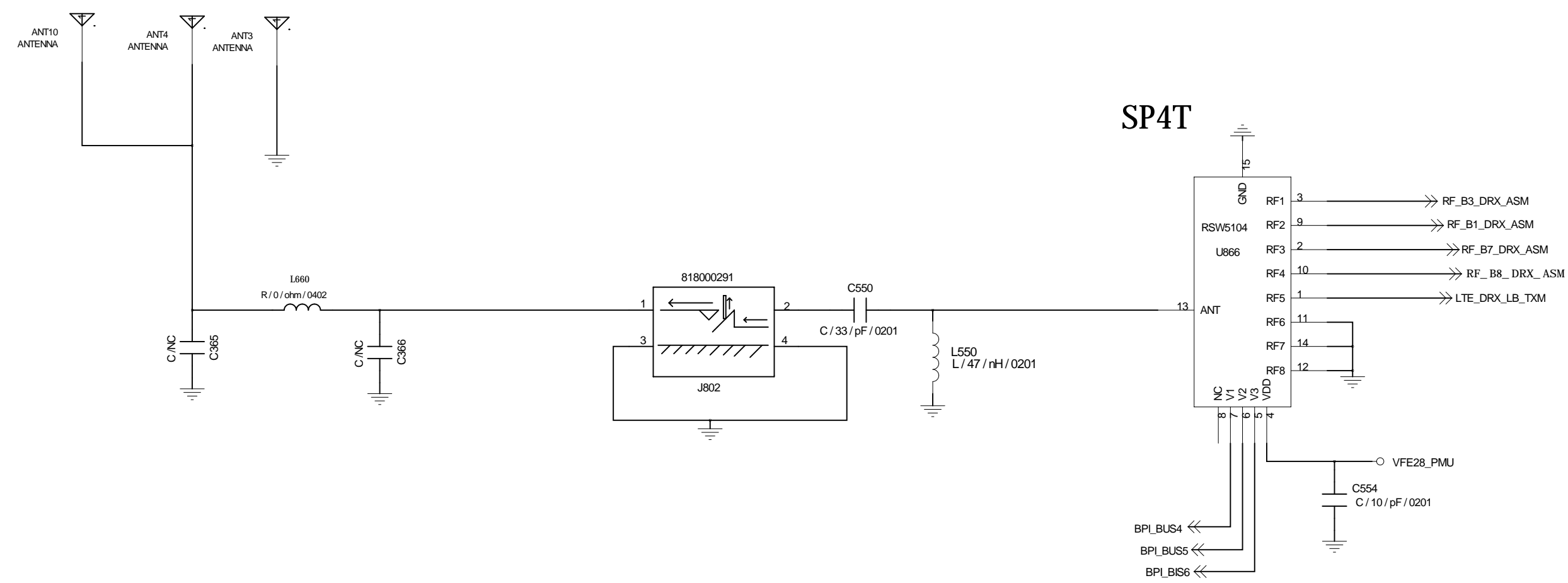
### LTE\_B20



### GSM\_WCDMA\_B5\_NC



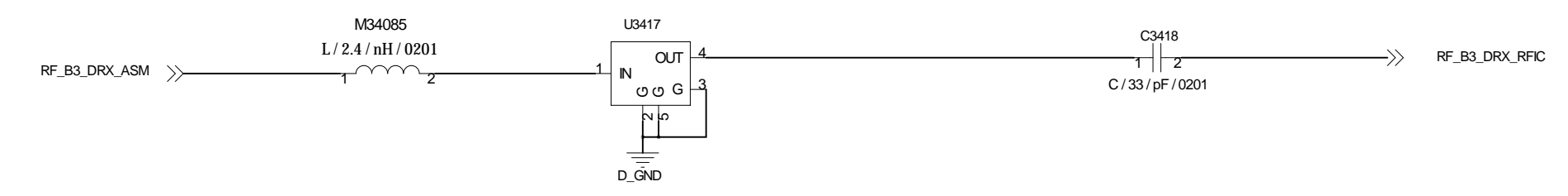
### DRX Antenna



### B1 DRX



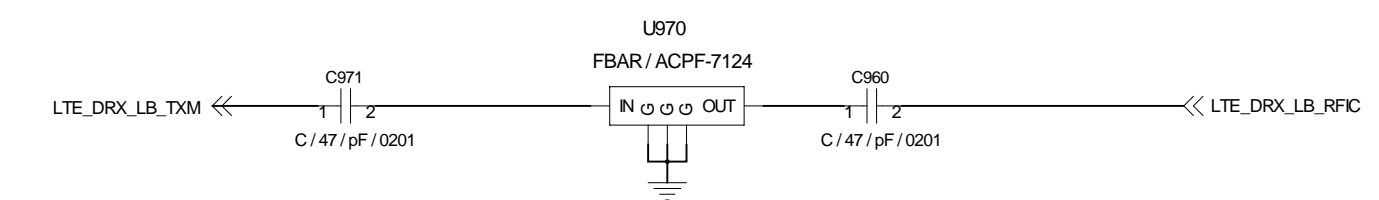
### B3 DRX



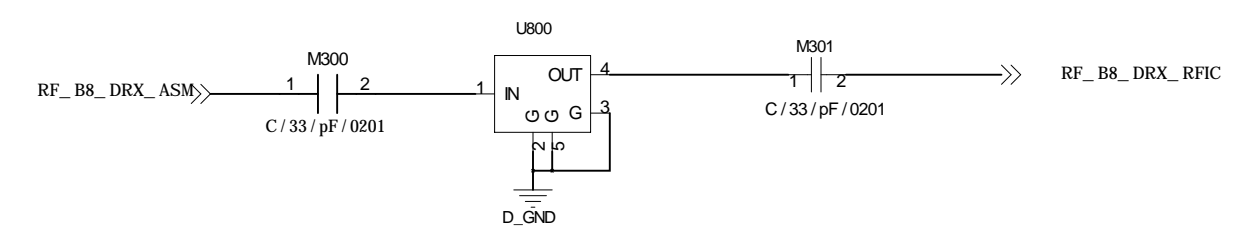
### B7 DRX



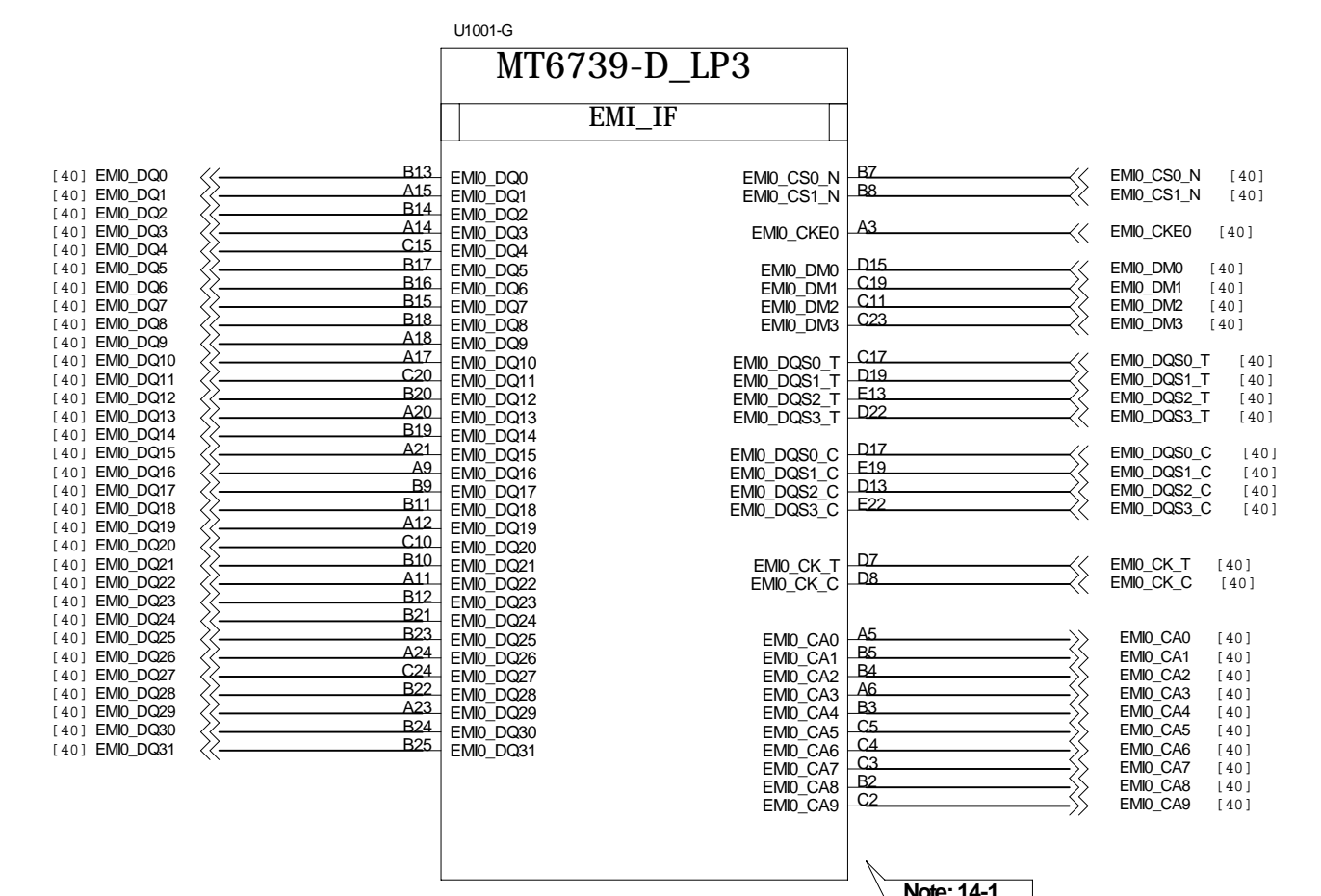
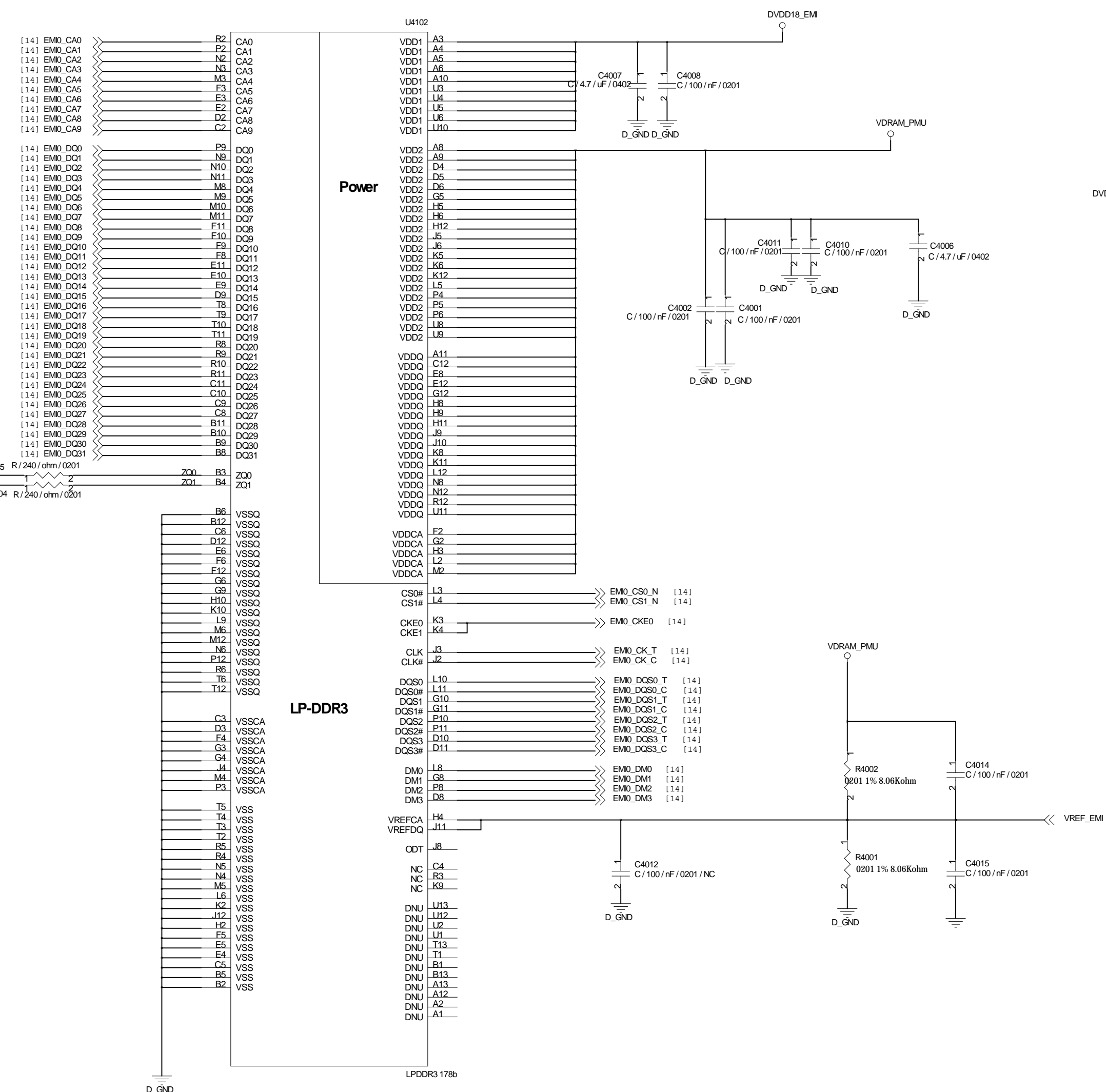
### B20



### B8

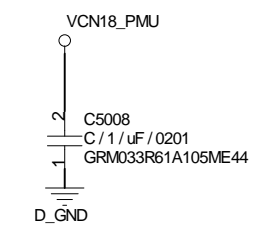
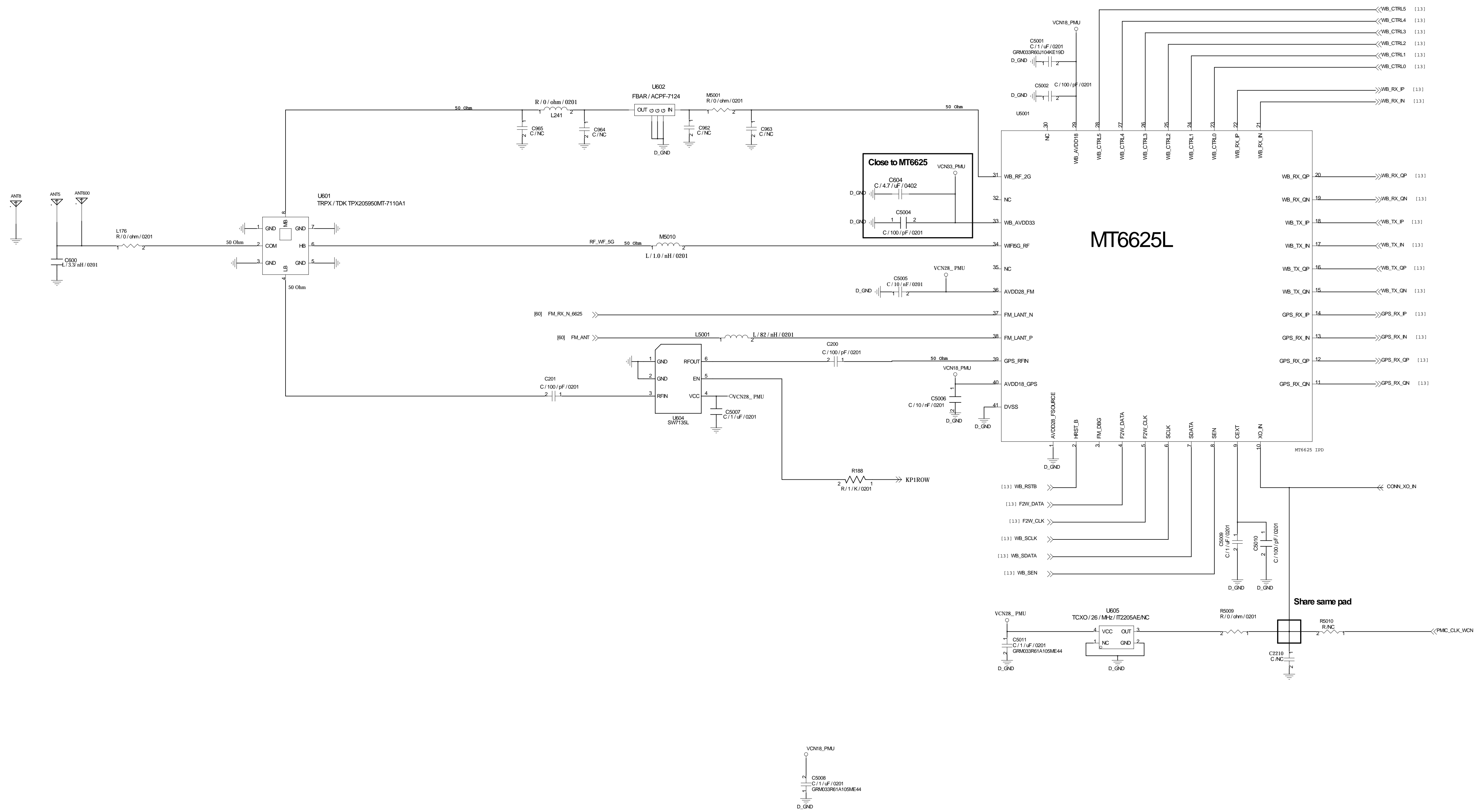


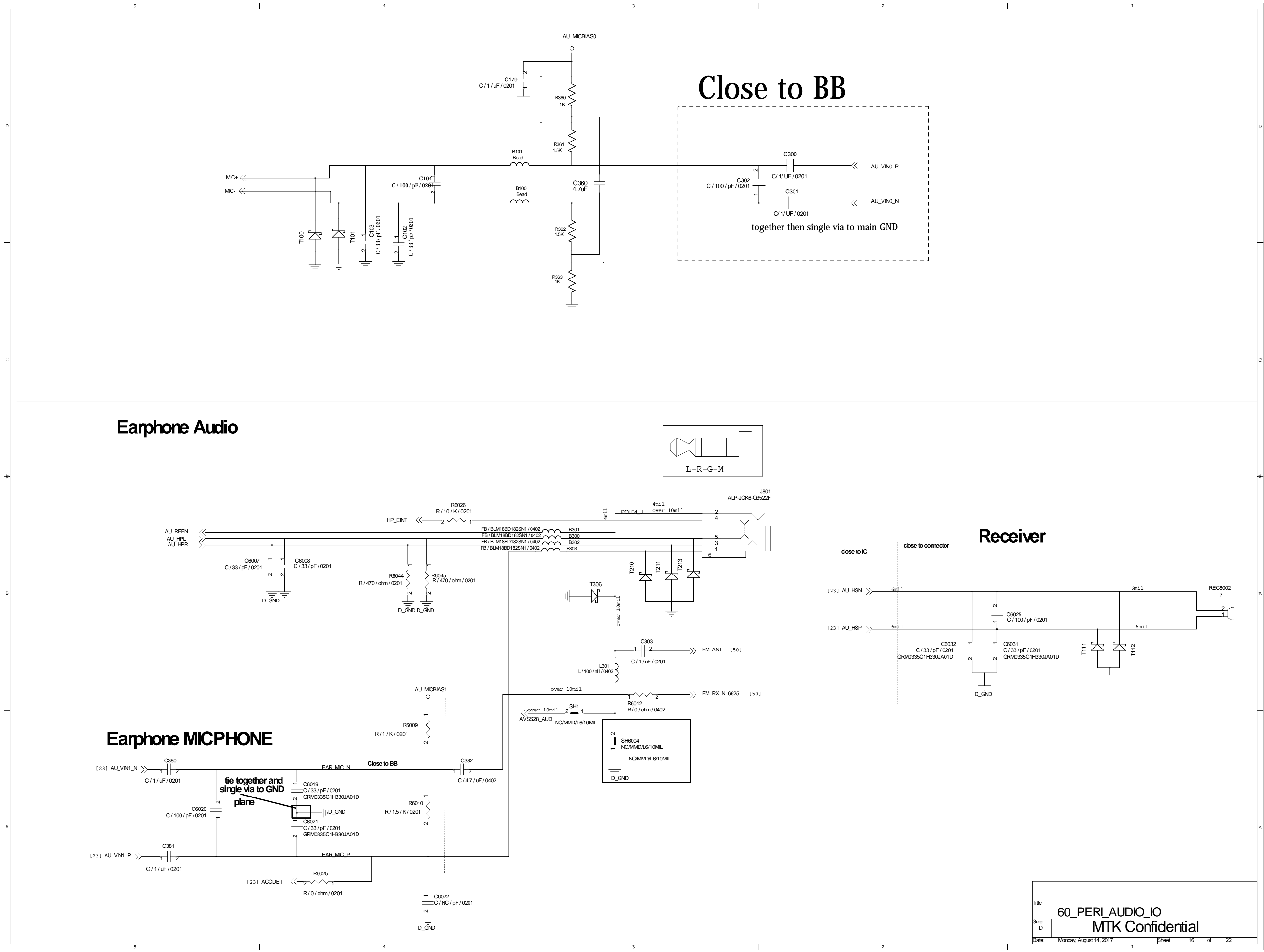
# discrete LP3



**Schematic design notice of "14\_BB\_3" page.**

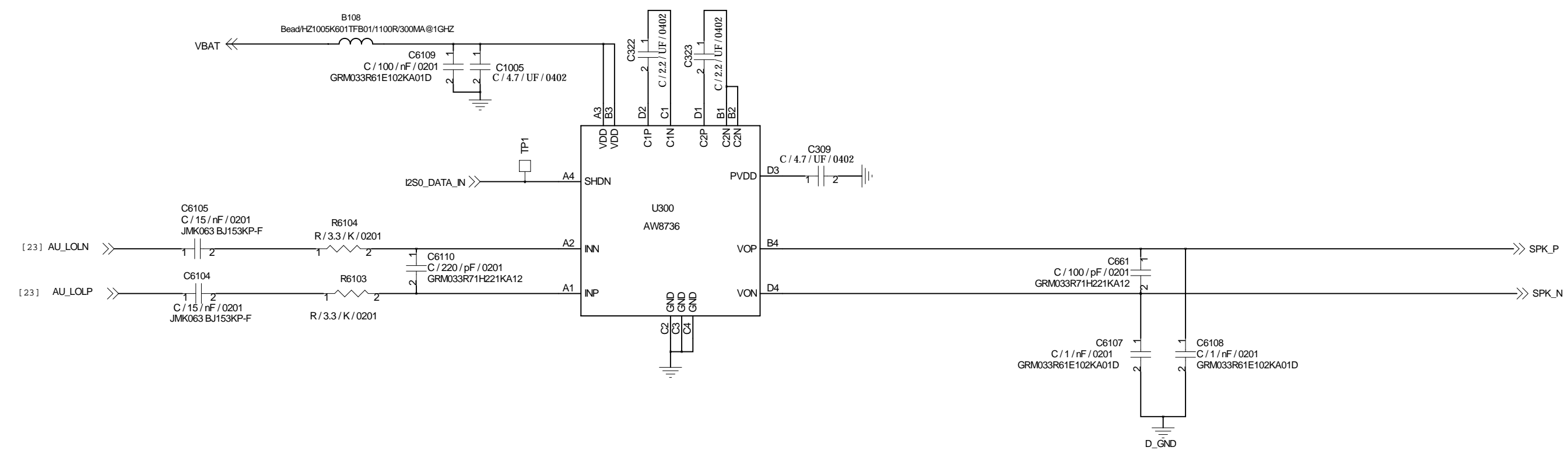
Note 14-1: MT6739 LPDDR3-eMCP/Discrete LPDDR3/LPDDR2-eMCP ball map is different. Base on the memory you select connect BB-Memory with correct ball map



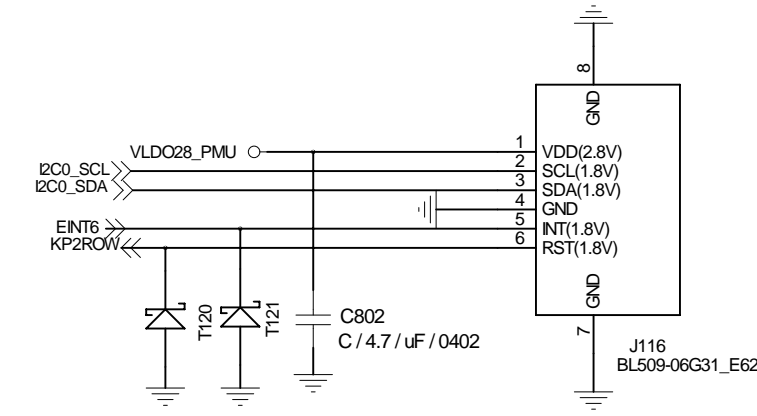




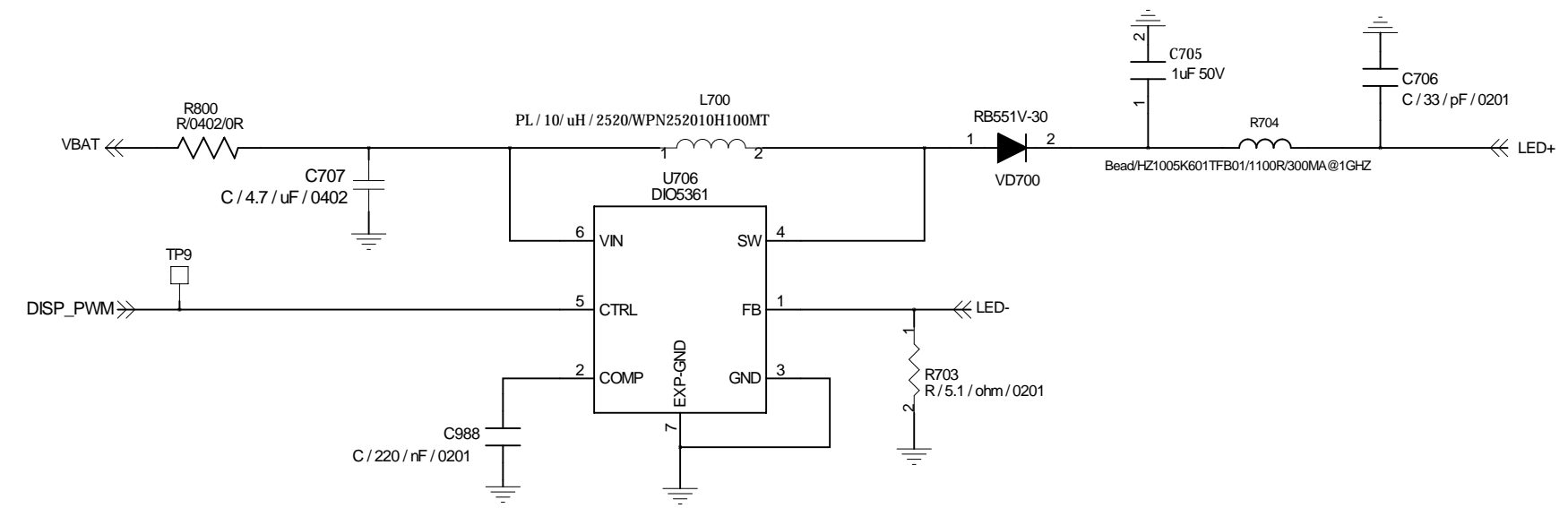
### Speaker Amplifier



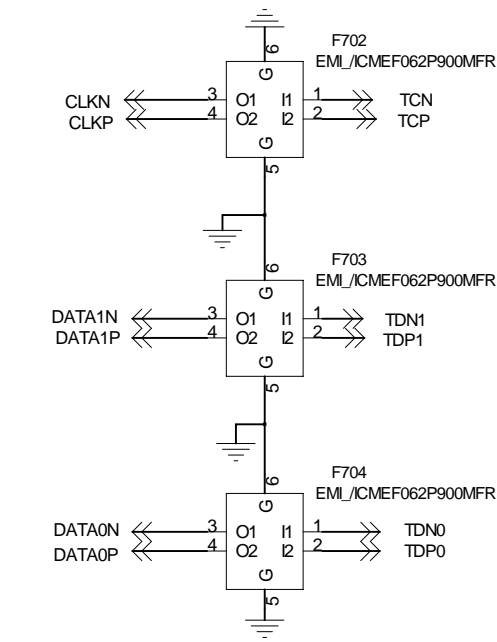
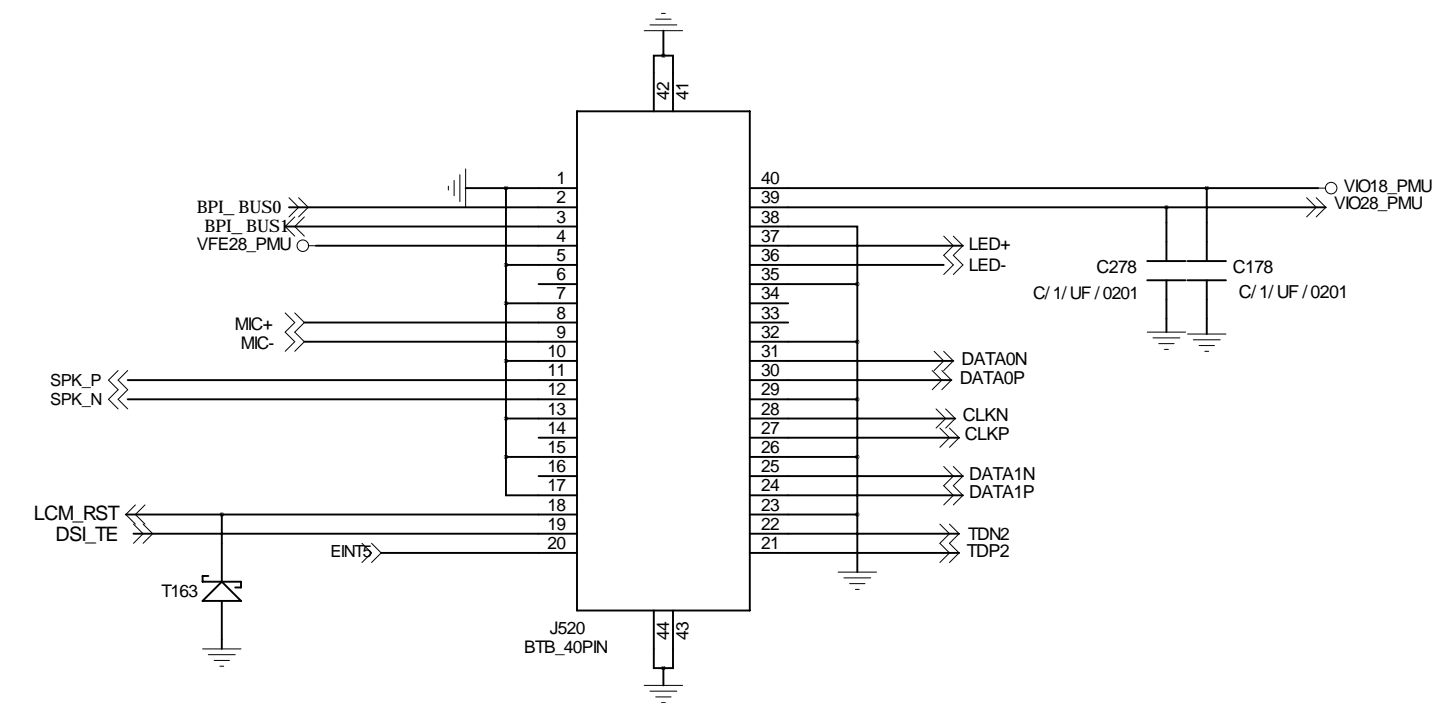
# CTP

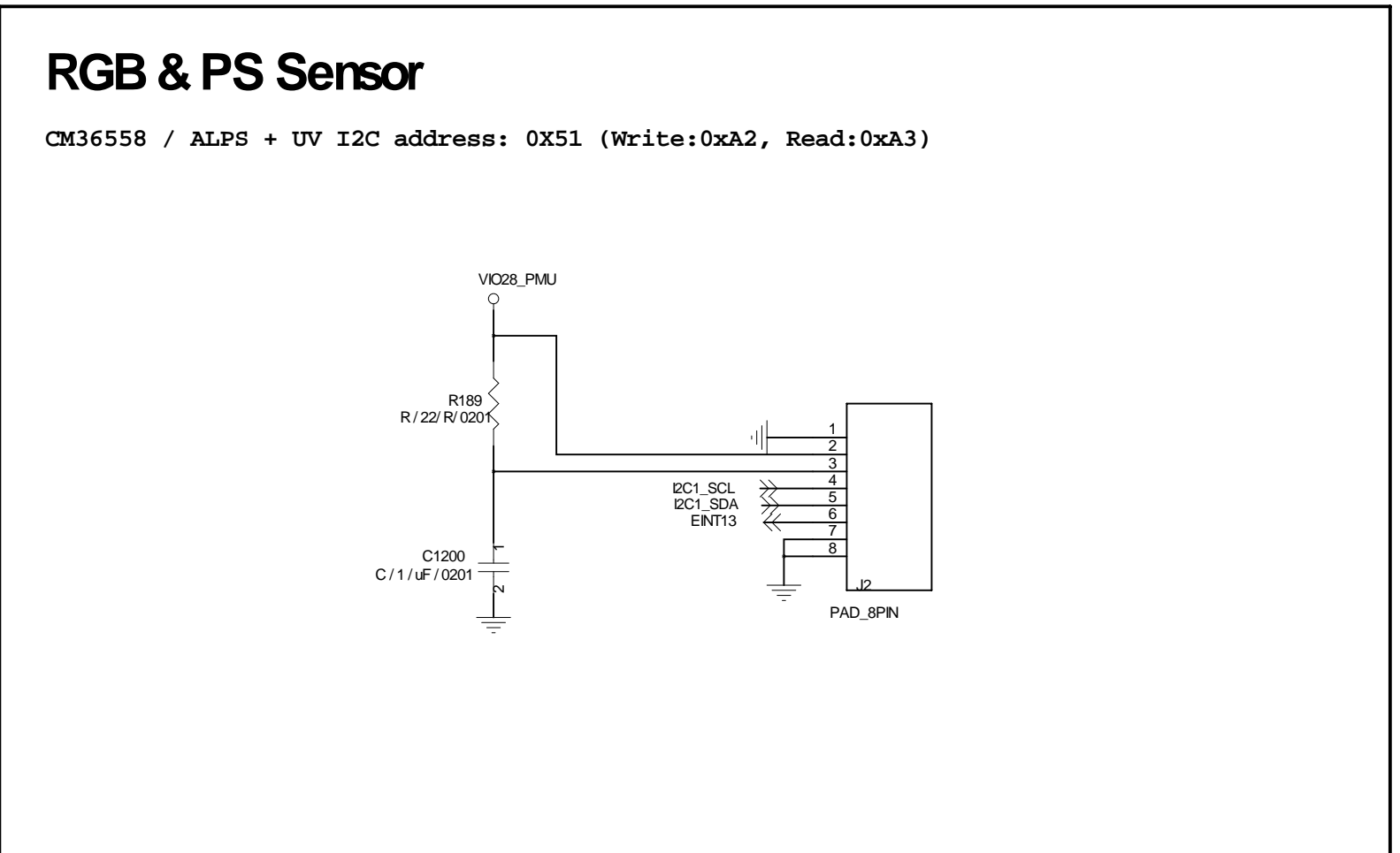
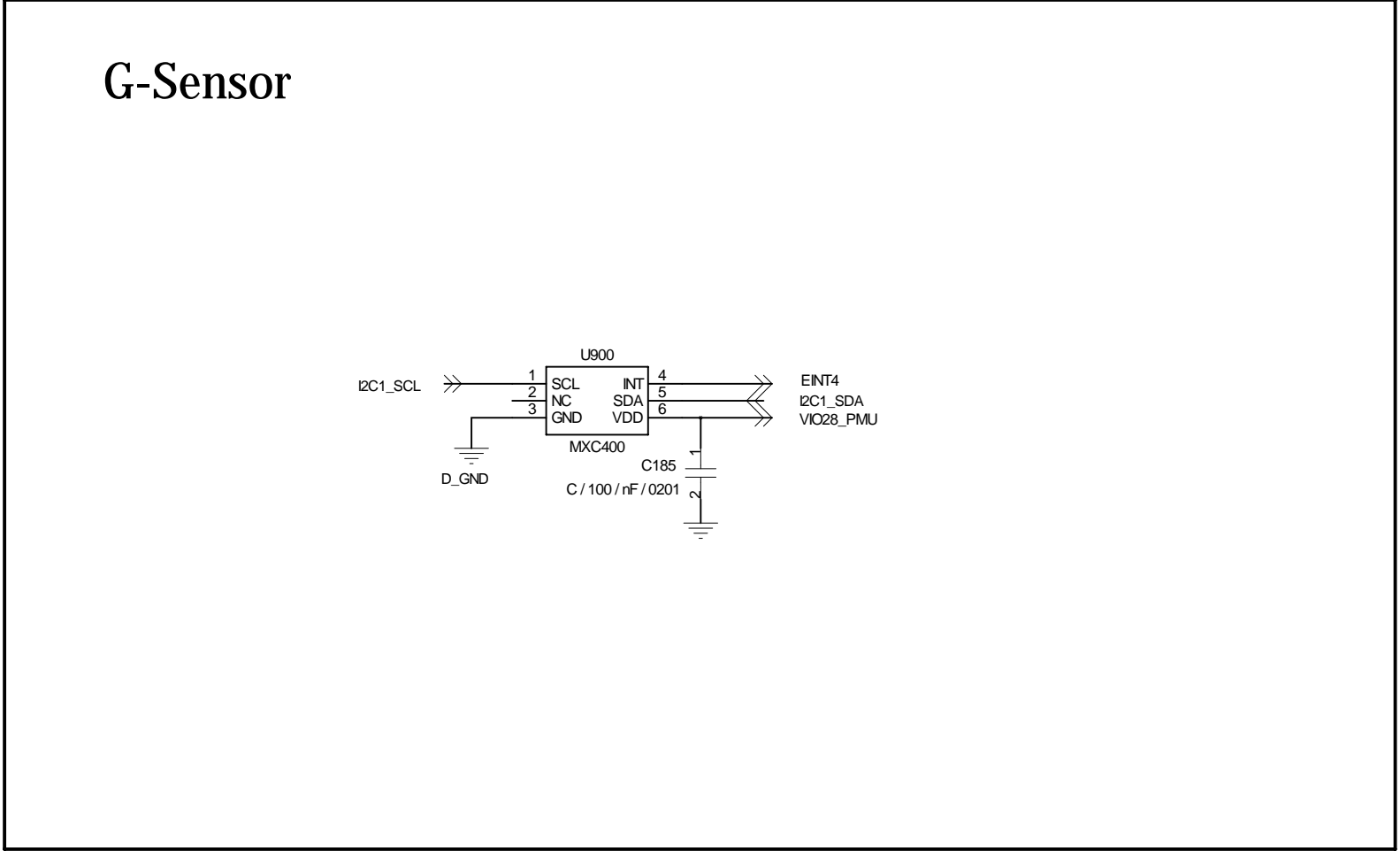
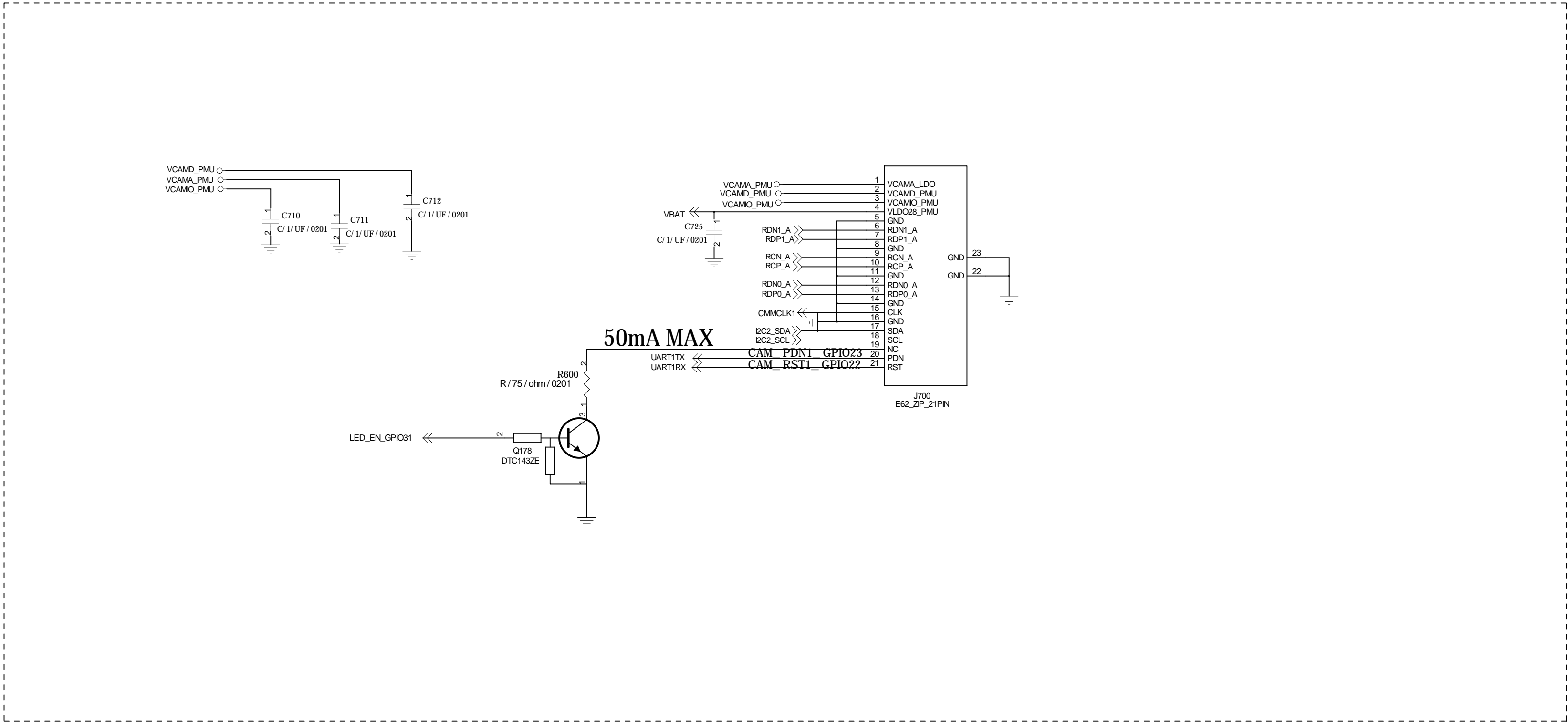
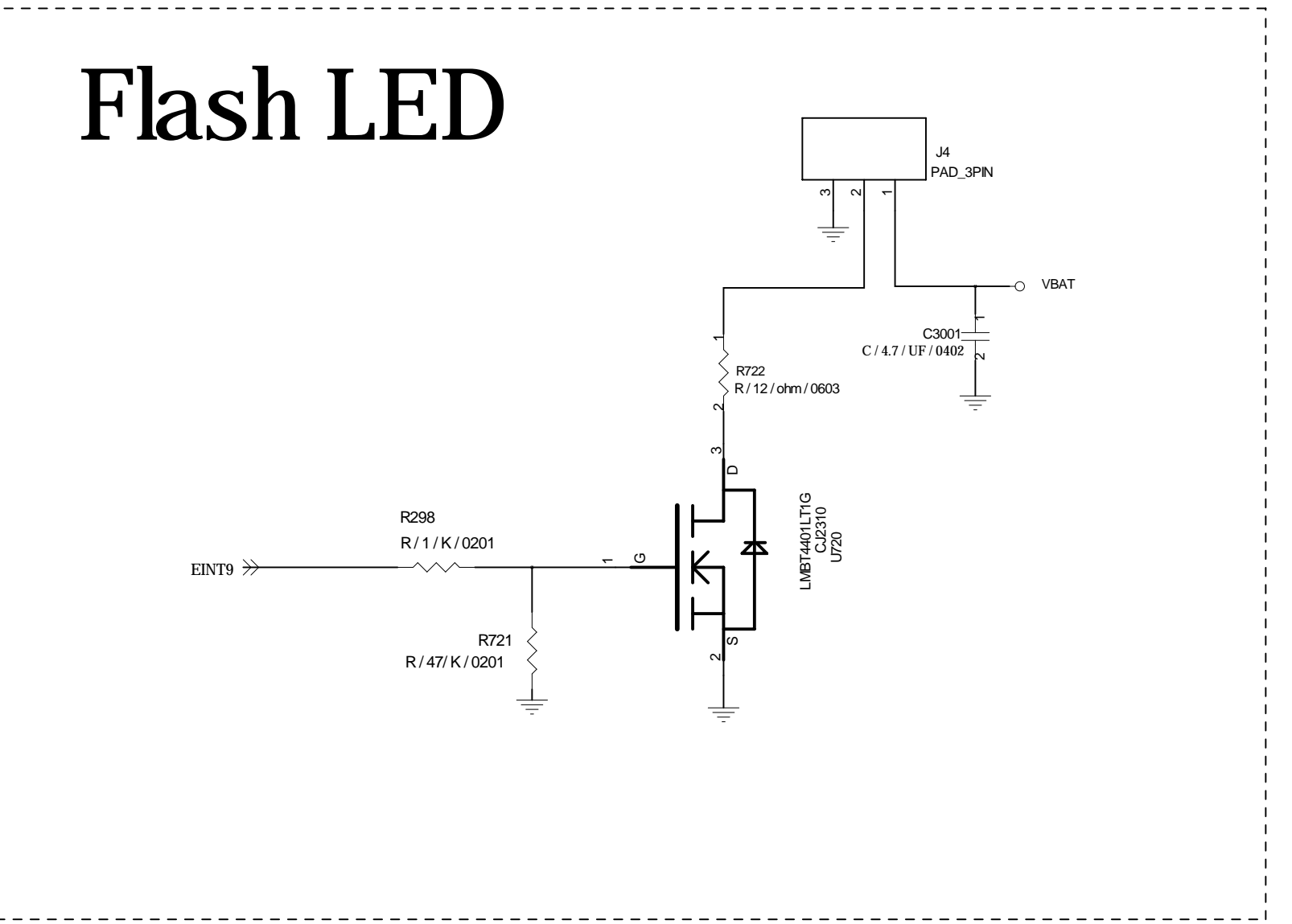
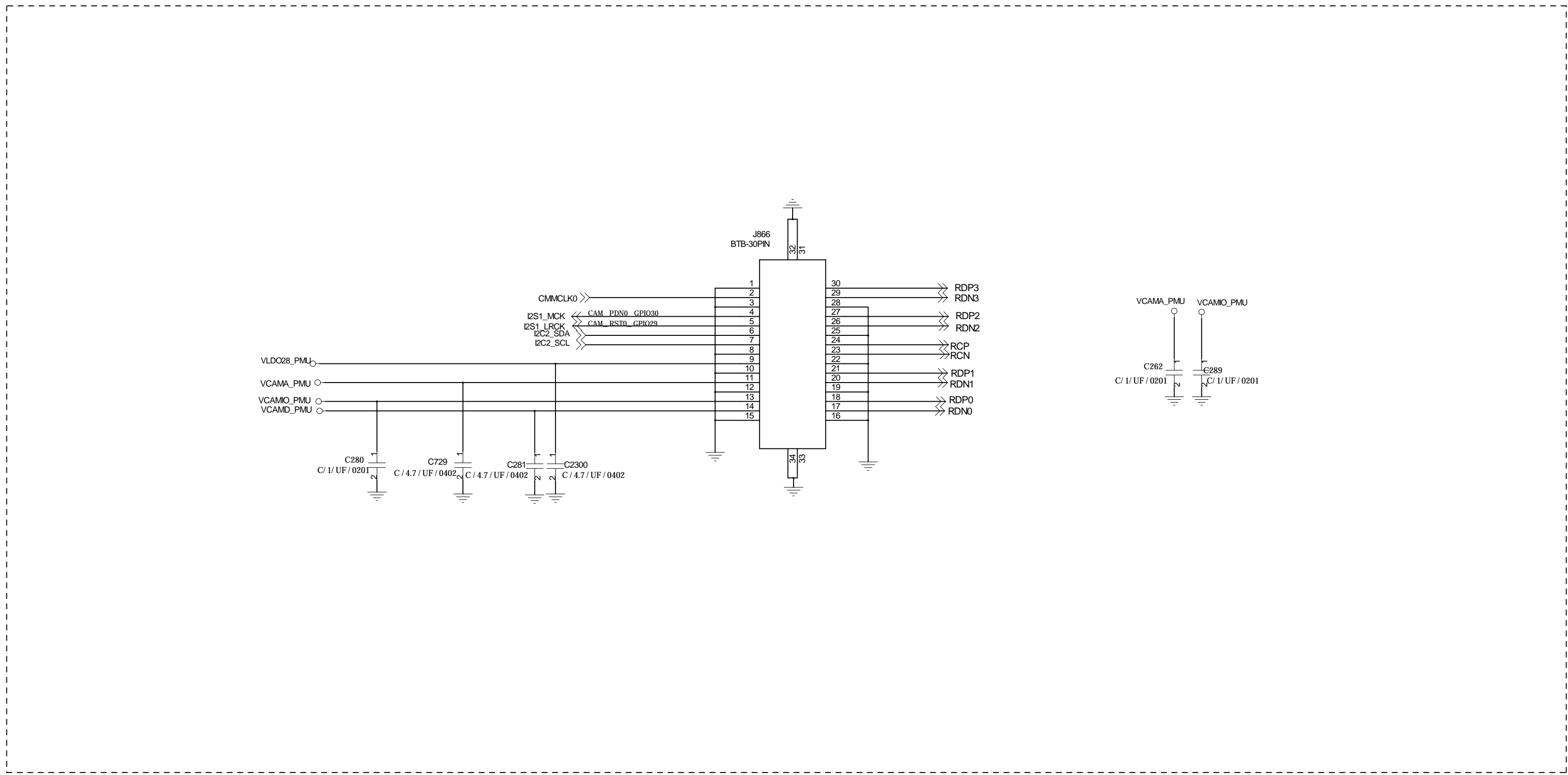


# LCM Backlight LED Driver

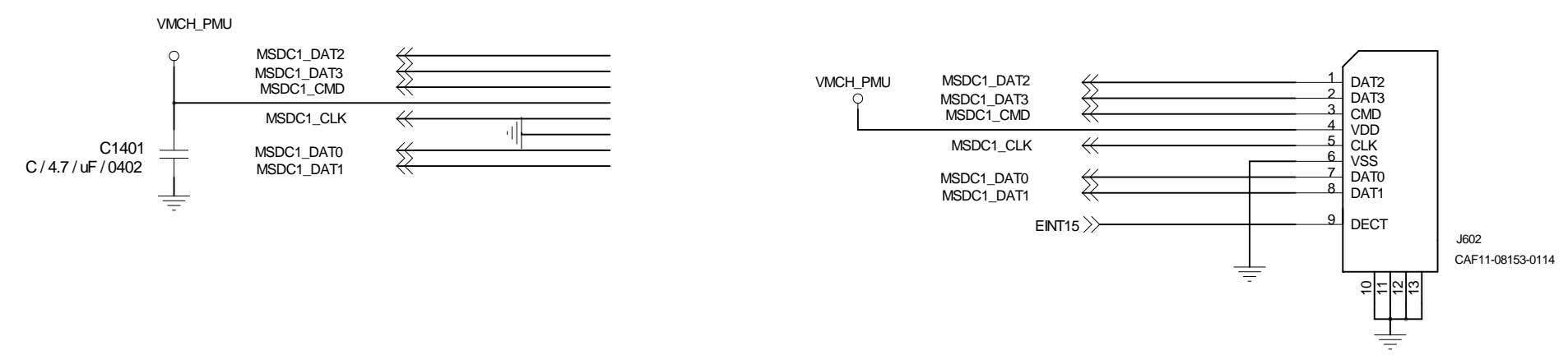


# LCM Connector

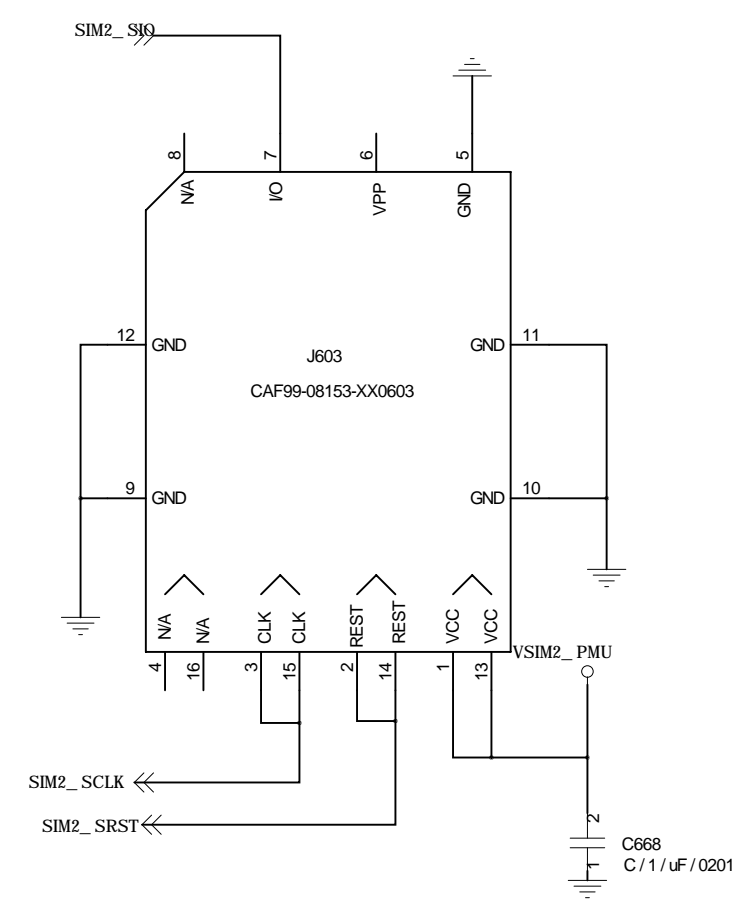




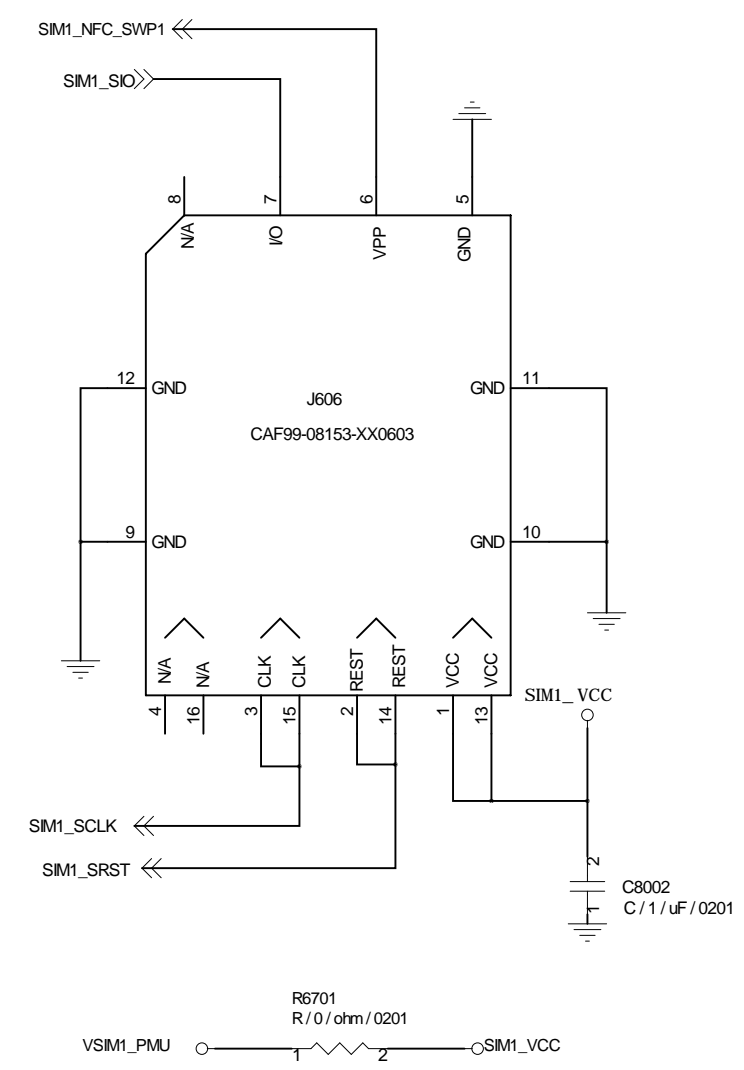
### T-CARD

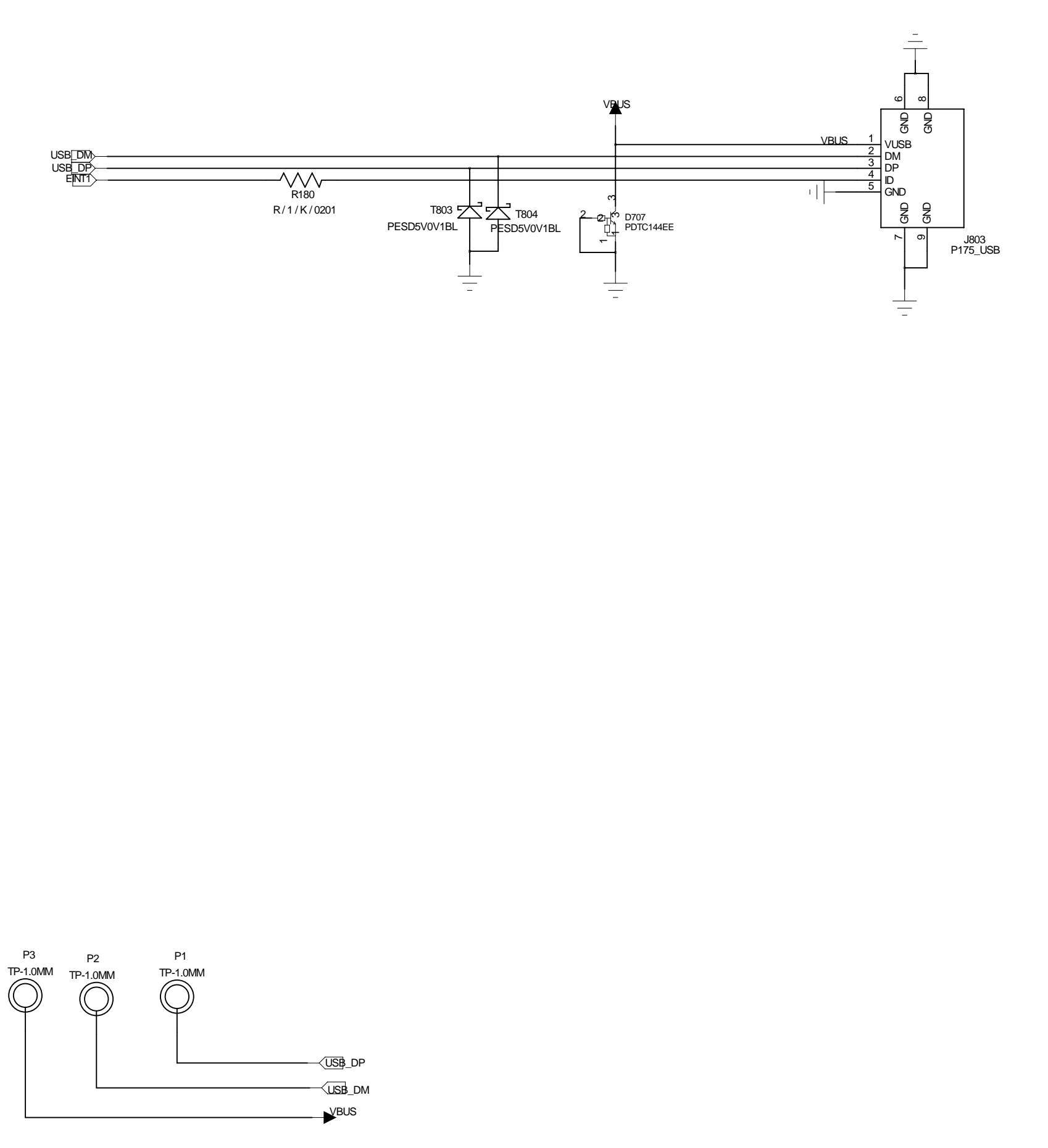
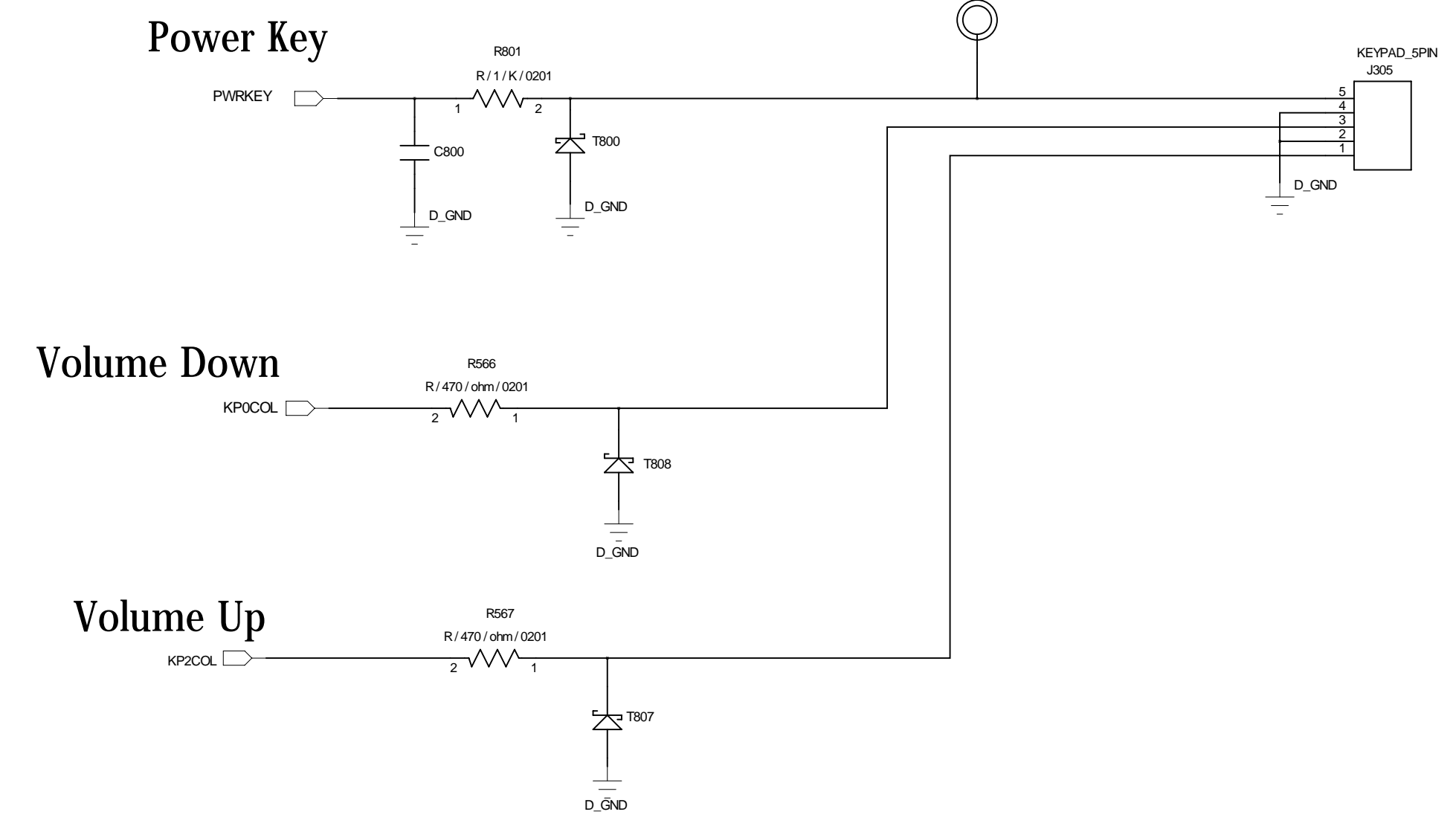


### SIM2



### SIM1





# 153 ball eMMC

